

LSM303AH

Ultra-compact high-performance eCompass module: ultra-low-power 3D accelerometer and 3D magnetometer

Datasheet - production data



Features

- 3 magnetic field channels and 3 acceleration channels
- ±50 gauss magnetic dynamic range
- ±2/±4/±8/±16 *g* selectable acceleration full scales
- Anti-aliasing filter
- 16-bit data output
- SPI / I²C serial interfaces
- Analog supply voltage 1.71 V to 1.98 V
- Programmable interrupt generators for freefall, motion and magnetic field detection
- Embedded self-test
- Embedded 256-level FIFO
- Embedded temperature sensor
- Embedded digital functions: step detector, step counter, significant motion and tilt
- ECOPACK[®], RoHS and "Green" compliant

Applications

- Tilt-compensated compasses
- Map rotation
- Position and free-fall detection
- Motion-activated functions
- Click/double-click recognition
- Pedometers
- Intelligent power saving for handheld devices
- Display orientation
- · Gaming and virtual reality input devices
- Impact recognition and logging
- Vibration monitoring and compensation

Description

The LSM303AH is an ultra-low-power highperformance system-in-package featuring a 3D digital linear acceleration sensor and a 3D digital magnetic sensor.

The LSM303AH has user-selectable linear acceleration full scales of $\pm 2g/\pm 4g/\pm 8g/\pm 16 g$ and is capable of measuring accelerations with output data rates from 1 Hz to 6400 Hz. The device has a magnetic field dynamic range of ± 50 gauss with output data rates from10 Hz to 100 Hz. The LSM303AH includes an I²C serial bus interface that supports standard, fast mode, fast mode plus, and high-speed (100 kHz, 400 kHz, 1 MHz, and 3.4 MHz) and an SPI serial standard interface.

The LSM303AH has an integrated 256-level firstin, first-out (FIFO) buffer allowing the user to store data in order to limit intervention by the host processor. The FIFO buffer applies only to the accelerometer.

The embedded self-test capability allows the user to check the functioning of the sensor in the final application.

The system can be configured to generate an interrupt signal for free-fall, motion detection and magnetic field detection. The magnetic and accelerometer blocks can be enabled or put into power-down mode separately.

The LSM303AH is available in a plastic land grid array package (LGA) and is guaranteed to operate over an extended temperature range from -40 °C to +85 °C.

Table 1. Device summary

Part number	Temp. range [°C]	Package	Packaging	
LSM303AH	-40 to +85	LGA-12	Tray	
LSM303AHTR	-40 to +85	LGA-12	Tape and reel	

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This is information on a product in full production.

1/82

Contents

1	Bloc	k diagr	am and pin description	. 10
	1.1	Block	diagram	. 10
	1.2	Pin de	scription	. 11
2	Mod	ule spe	cifications	. 13
	2.1	Senso	r characteristics	. 13
	2.2	Tempe	erature sensor characteristics	. 15
	2.3	Electri	cal characteristics	. 15
	2.4	Comm	unication interface characteristics	. 16
		2.4.1	SPI - serial peripheral interface	. 16
		2.4.2	I ² C - inter-IC control interface	. 17
	2.5	Absolu	ite maximum ratings	. 19
3	Tern	ninology	/	20
	3.1	Sensit	ivity	. 20
		3.1.1	Linear acceleration sensor sensitivity	. 20
		3.1.2	Magnetic sensor sensitivity	. 20
	3.2	Zero-g	level	. 20
	3.3	Zero-g	auss level	. 20
	3.4	Magne	etic dynamic range	. 20
4	Fund	ctionalit	y	. 21
	4.1	Magne	etometer	. 21
		4.1.1	Magnetometer power modes	. 21
		4.1.2	Magnetometer offset cancellation	. 23
		4.1.3	Magnetometer interrupt	. 23
		4.1.4	Magnetometer hard-iron compensation	. 25
		4.1.5	Magnetometer self-test	. 25
	4.2	Accele	rometer	. 27
		4.2.1	Accelerometer power modes	. 27
		4.2.2	Accelerometer 6D / 4D orientation detection	. 29
		4.2.3	Accelerometer activity/inactivity function	. 29
		4.2.4	Accelerometer self-test	. 29

DocID027766 Rev 7



2/82

		4.2.5	Accelerometer data stabilization time vs. ODR setting	31
		4.2.6	Accelerometer anti-aliasing filter	31
	4.3	IC interf	ace	31
	4.4	FIFO		32
		4.4.1	Bypass mode	32
		4.4.2	FIFO mode	33
		4.4.3	Continuous mode	33
		4.4.4	Continuous-to-FIFO mode	33
		4.4.5	Bypass-to-Continuous mode	35
		4.4.6	Module-to-FIFO	36
	4.5	Embedo	led functions	36
		4.5.1	Step detector/Step counter	37
		4.5.2	Significant motion	37
	4.6	Factory	calibration	38
_	A P			
5			ints	
	5.1		g information	
	5.2	High-cu	rrent wiring effects	40
6	Digita	l interfa	ICes	11
•	6.1	-	al interface	
	0.1	6.1.1	I ² C operation	
	6.2		interface	
	0.2	6.2.1	Accelerometer SPI write	
		6.2.2	Accelerometer SPI read in 3-wire mode	-
		6.2.3		46
		6.2.4	Magnetometer SPI read in 3-wire mode	47
			С С	
7	Regis	ter map	ping	18
8	Regis	ter des	cription	51
	8.1	Module_	_8bit_A (0Ch)	51
	8.2	WHO_A	.M_I_A (0Fh)	51
	8.3	CTRL1	A (20h)	51
	8.4			52
	8.4 8.5	CTRL2_	_A (21h)	



8.6	CTRL4_A (23h)
8.7	CTRL5_A (24h)
8.8	FIFO_CTRL_A (25h) 56
8.9	OUT_T_A (26h) 57
8.10	STATUS_A (27h) 57
8.11	OUT_X_L_A (28h) 58
8.12	OUT_X_H_A (29h) 58
8.13	OUT_Y_L_A (2Ah) 58
8.14	OUT_Y_H_A (2Bh) 58
8.15	OUT_Z_L_A (2Ch) 59
8.16	OUT_Z_H_A (2Dh) 59
8.17	FIFO_THS_A (2Eh) 59
8.18	FIFO_SRC_A (2Fh) 59
8.19	FIFO_SAMPLES_A (30h) 60
8.20	TAP_6D_THS_A (31h) 60
8.21	INT_DUR_A (32h) 61
8.22	WAKE_UP_THS_A (33h) 61
8.23	WAKE_UP_DUR_A (34h) 62
8.24	FREE_FALL_A (35h) 62
8.25	STATUS_DUP_A (36h) 63
8.26	WAKE_UP_SRC_A (37h) 64
8.27	TAP_SRC_A (38h) 64
8.28	6D_SRC_A (39h) 65
8.29	STEP_COUNTER_MINTHS_A (3Ah) 65
8.30	STEP_COUNTER_L_A (3Bh) 66
8.31	STEP_COUNTER_H_A (3Ch) 66
8.32	FUNC_CK_GATE_A (3Dh) 66
8.33	FUNC_SRC_A (3Eh) 67
8.34	FUNC_CTRL_A (3Fh) 68
8.35	OFFSET_X_REG_L_M (45h) and OFFSET_X_REG_H_M (46h) 68
8.36	OFFSET_Y_REG_L_M (47h) and OFFSET_Y_REG_H_M (48h) 68
8.37	OFFSET_Z_REG_L_M (49h) and OFFSET_Z_REG_H_M (4Ah) 68
8.38	WHO_AM_I_M (4Fh) 68



	8.39	CFG_REG_A_M (60h) 6	9
	8.40	CFG_REG_B_M (61h) 7	0
	8.41	CFG_REG_C_M (62h) 7	1
	8.42	INT_CTRL_REG_M (63h) 7	1
	8.43	INT_SOURCE_REG_M (64h) 7	2
	8.44	INT_THS_L_REG_M (65h) 7	2
	8.45	INT_THS_H_REG_M (66h) 7	2
	8.46	STATUS_REG_M (67h) 7	3
	8.47	OUTX_L_REG_M, OUTX_H_REG_M (68h - 69h)	3
	8.48	OUTY_L_REG_M, OUTY_H_REG_M (6Ah - 6Bh)	4
	8.49	OUTZ_L_REG_M, OUTZ_H_REG_M (6Ch - 6Dh)	4
9	Adva	nced configuration register mapping7	5
9 10		nced configuration register mapping	
-			6
-	Adva	nced configuration registers description	6 6
-	Adva 10.1	nced configuration registers description	6 6
-	Adva 10.1 10.2	nced configuration registers description	6 6 6
-	Adva 10.1 10.2 10.3 10.4	nced configuration registers description	6 6 6 7
10	Adva 10.1 10.2 10.3 10.4	nced configuration registers description 7 PEDO_DEB_REG_A (2Bh) 7 SM_THS_A (34h) 7 STEP_COUNT_DELTA_A (3Ah) 7 CTRL2_A (3Fh) 7	6 6 6 7 8
10	Adva 10.1 10.2 10.3 10.4 Packa	nced configuration registers description 7 PEDO_DEB_REG_A (2Bh) 7 SM_THS_A (34h) 7 STEP_COUNT_DELTA_A (3Ah) 7 CTRL2_A (3Fh) 7 age information 7	6 6 6 7 8 8



List of tables

Table 1.	Device summary	. 1
Table 2.	Pin description	
Table 3.	Sensor characteristics.	13
Table 4.	Temperature sensor characteristics	15
Table 5.	Electrical characteristics	15
Table 6.	SPI slave timing values.	
Table 7.	I ² C slave timing values (standard and fast mode)	
Table 8.	I ² C slave timing values (fast mode plus and high speed)	
Table 9.	Absolute maximum ratings	
Table 10.	RMS noise of operating modes.	
Table 11.	Current consumption of operating modes	
Table 12.	Operating mode and turn-on time	
Table 13.	Maximum ODR in single measurement mode (HR and LP modes)	
Table 14.	Accelerometer operating modes	
Table 15.	Low-pass filter in low-power, high-resolution and high-frequency modes	
Table 16.	Current consumption of operating modes.	
Table 17.	Number of samples to be discarded	
Table 18.	ODR function settings.	
Table 19.	Pin status	
Table 20.	Serial interface pin description	
Table 20. Table 21.	I ² C terminology	
Table 21.	Transfer when master is writing one byte to slave	
Table 22. Table 23.		
Table 23.	Transfer when master is writing multiple bytes to slave	
	Transfer when master is receiving (reading) one byte of data from slave	
Table 25.	Transfer when master is receiving (reading) multiple bytes of data from slave	
Table 26.	SAD+Read/Write patterns	
Table 27.	SAD + Read/Write patterns	
Table 28.	Register map.	
Table 29.	Module_8bit_A register	
Table 30.	Module_8bit_A register description.	
Table 31.	WHO_AM_I_A register default values	
Table 32.	CTRL1_A register	
Table 33.	CTRL1_A register description.	
Table 34.	ODR register setting: power down (PD) and low power (LP)	
Table 35.	ODR register setting: high resolution (HR) and high frequencies (HF)	
Table 36.	CTRL2_A register	
Table 37.	CTRL2_A register description	
Table 38.	CTRL3_A register	
Table 39.	CTRL3_A register description	
Table 40.	Self-test mode selection	54
Table 41.	CTRL4_A register	
Table 42.	CTRL4_A register description	54
Table 43.	CTRL5_A register	
Table 44.	CTRL5_A register description	55
Table 45.	FIFO_CTRL_A register.	56
Table 46.	FIFO_CTRL_A register description.	56
Table 47.	FIFO mode selection.	56
Table 48.	OUT_T_A register	57



Table 49.	OUT_T_A register description	
Table 50.	STATUS_A register	
Table 51.	STATUS_A register description	
Table 52.	OUT_X_L_A register default values	
Table 53.	OUT_X_H_A register default values	
Table 54.	OUT_Y_L_A register default values	
Table 55.	OUT_Y_H_A register default values	
Table 56.	OUT_Z_L_A register default values	
Table 57.	OUT_Z_H_A register default values	
Table 58.	FIFO_THS_A register	
Table 59.	FIFO_SRC_A register	
Table 60.	FIFO_SRC register description	
Table 61.	FIFO_SAMPLES_A register	
Table 62.	FIFO_SAMPLES_A register description	
Table 63.	TAP_6D_THS_A register	
Table 64.	TAP_6D_THS_A register description	
Table 65.	4D/6D threshold setting FS @ 2 g	
Table 66.	INT_DUR_A register	
Table 67.	INT_DUR_A register description.	
Table 68.	WAKE_UP_THS_A register	
Table 69.	WAKE_UP_THS_A register description	
Table 70.	WAKE_UP_DUR_A register	
Table 71.	WAKE_UP_DUR_A register description	
Table 72.	FREE_FALL_A register	
Table 73.	FREE_FALL_A register description	2
Table 74.	FREE_FALL_A threshold decoding @ 2 g FS6.	2
Table 75.	STATUS_DUP_A register	
Table 76.	STATUS_DUP_A register description	
Table 77.	WAKE_UP_SRC_A register	
Table 78.	WAKE_UP_SRC_A register description	
Table 79.	TAP_SRC_A register	
Table 80.	TAP_SRC_A register description	
Table 81.	6D_SRC_A register	
Table 82.	6D_SRC_A register description	
Table 83.	STEP_COUNTER_MINTHS_A configuration register	
Table 84.	STEP_COUNTER_MINTHS_A configuration register description	
Table 85.	STEP_COUNTER_L_A configuration register	
Table 86.	STEP_COUNTER_L_A configuration register description	
Table 87.	STEP_COUNTER_H_A register	
Table 88.	STEP_COUNTER_H_A register description	
Table 89.	FUNC_CK_GATE_A register	
Table 90.	FUNC_CK_GATE_A register description	
Table 91.	FUNC_SRC_A register	
Table 92.	FUNC_SRC_A register description	
Table 93.	FUNC_CTRL_A register	
Table 94.	FUNC_CTRL_A register description	
Table 95.	CFG_REG_A_M register	
Table 96.	CFG_REG_A_M register description	
Table 97.	Output data rate configuration	
Table 98.	System mode	
Table 99.	CFG_REG_B_M register	
Table 100.	CFG_REG_B_M register description	0



Table 101.	Digital low-pass filter
Table 102.	CFG_REG_C_M register
Table 103.	CFG_REG_C_M register description
Table 104.	INT_CRTL_REG_M register
Table 105.	INT_CTRL_REG_M register description
Table 106.	INT_SOURCE_REG_M register
Table 107.	INT_SOURCE_REG_M register description
Table 108.	INT_THS_L_REG_M register
Table 109.	INT_THS_L_REG_M register description
Table 110.	INT_THS_H_REG_M register72
Table 111.	INT_THS_H_REG_M register description72
Table 112.	STATUS_REG_M register
Table 113.	STATUS_REG_M register description
Table 114.	OUTX_L_REG_M register
Table 115.	OUTX_H_REG_M register
Table 116.	OUTY_L_REG_M register
Table 117.	OUTY_H_REG_M register
Table 118.	OUTZ_L_REG_M register
Table 119.	OUTZ_H_REG_M register
Table 120.	Register map - advanced configuration functions
Table 121.	PEDO_DEB_REG_A register default values
Table 122.	PEDO_DEB_REG_A register description
Table 123.	SM_THS_A configuration register
Table 124.	SM_THS_A configuration register description
Table 125.	STEP_COUNT_DELTA_A configuration register
Table 126.	STEP_COUNT_DELTA_A configuration register description
Table 127.	CTRL2_A configuration register
Table 128.	CTRL2_A configuration register description
Table 129.	Reel dimensions for carrier tape of LGA-12 package
Table 130.	Document revision history



List of figures

Figure 1.	Block diagram	. 10
Figure 2.	Pin connections	. 11
Figure 3.	SPI slave timing diagram	. 16
Figure 4.	I ² C slave timing diagram	. 18
Figure 5.	Interrupt function	
Figure 6.	Magnetometer self-test procedure	. 26
Figure 7.	Accelerometer self-test procedure	
Figure 8.	Continuous-to-FIFO mode	
Figure 9.	Trigger event to FIFO for Continuous-to-FIFO mode	
Figure 10.	Bypass-to-Continuous mode	
Figure 11.	Trigger event to FIFO for Bypass-to-Continuous mode	. 35
Figure 12.	Module-to-FIFO mode example	. 36
Figure 13.	LSM303AH electrical connections	. 39
Figure 14.	Read and write protocol	. 44
Figure 15.	Accelerometer SPI write protocol	. 45
Figure 16.	Accelerometer multiple byte SPI write protocol (2-byte example)	. 45
Figure 17.	Accelerometer SPI read protocol in 3-wire mode	. 46
Figure 18.	Magnetometer SPI write protocol	. 46
Figure 19.	Magnetometer multiple byte SPI write protocol (2-byte example)	. 47
Figure 20.	Magnetometer SPI read protocol in 3-wire mode	. 47
Figure 21.	LGA-12 2x2x1 mm package outline and mechanical data	
Figure 22.	Carrier tape information for LGA-12 package	. 79
Figure 23.	LGA-12 package orientation in carrier tape	. 79
Figure 24.	Reel information for carrier tape of LGA-12 package	. 80



1 Block diagram and pin description

1.1 Block diagram



10/82



1.2 Pin description



Figure 2. Pin connections



Pin#	Name	Function
1	SCL SPC	I ² C serial clock (SCL) SPI serial port clock (SPC)
2	CS	 SPI enable I²C/SPI mode selection 1: SPI idle mode / I²C communication enabled; 0: SPI communication mode / I²C disabled
3	Reserved	Reserved, connected to GND
4	SDA SDI SDO	I ² C serial data (SDA) SPI serial data input (SDI) 3-wire interface serial data output (SDO)
5	C1	Capacitor connection (C1 = 220 nF)
6	GND	0 V
7	INT_MAG/DRDY	Magnetometer interrupt/data-ready signal
8	GND	0 V
9	Vdd	Power supply
10	Vdd_IO	Power supply for I/O pins
11	INT2_XL	Accelerometer interrupt 2
12	INT1_XL	Accelerometer interrupt 1

Table 2.	Pin description	ı



2 Module specifications

2.1 Sensor characteristics

@ Vdd = 1.8 V, T = 25 °C unless otherwise noted ^(a).

Symbol	Parameter	Test conditions	Min.	Typ. ⁽¹⁾	Max.	Unit
				±2		
LA_FS	Linear acceleration			±4		g
	measurement range			±8		
				±16		
M_FS	Magnetic dynamic range			±49.152		gauss
		@ FS ±2 g		0.061		
LA So	Sensitivity 16-bit ⁽²⁾	@ FS ±4 g		0.122		mg/digit
LA_30		@ FS ±8 g		0.244		mg/uigit
		@ FS ±16 g		0.488		
M_So	Magnetic sensitivity			1.5		mgauss/ LSB
LA_TCSo	Linear acceleration sensitivity change vs. temperature ⁽³⁾			0.01		%/°C
M_TCSo	Magnetic sensitivity change vs. temperature ⁽³⁾			±0.03		%/°C
LA_TyOff	Typical zero- <i>g</i> level offset accuracy ⁽⁴⁾⁽⁵⁾			±30		m <i>g</i>
M_TyOff	Magnetic sensor offset	With offset cancellation ⁽⁶⁾⁽⁷⁾		0		mgauss
LA_TCOff	Zero-g level change vs. temp. ⁽³⁾	Max. delta from 25 °C		±0.2		mg/°C
M_TCOff	Magnetic sensor offset change vs. temp.	With offset cancellation ⁽⁶⁾	-0.3		+0.3	mgauss/ °C
LA_An	Linear acceleration RMS noise	ODR = 50 Hz, High-Resolution mode, FS = $\pm 2 g$		0.6		mg (RMS)
M_R	Magnetic RMS noise ⁽⁸⁾	High-performance mode		3		mgauss (RMS)
ST	Self-test positive difference ⁽⁹⁾ (accelerometer only)		70		1500	m <i>g</i>
M_ST	Magnetic self-test ⁽¹⁰⁾		15		500	mgauss
Тор	Operating temperature range		-40		+85	°C

Table 3. Sensor characteristics

1. Typical specifications are not guaranteed.

a. The product is factory calibrated at 1.8 V. The operational power supply range is from 1.71 V to 1.98 V.



- 2. Sensitivity calculated at 16-bit.
- 3. Measurements are performed in a uniform temperature setup and they are based on characterization data in a limited number of samples, not measured during final test for production.
- 4. Typical zero-g level offset value after MSL3 preconditioning.
- 5. Offset can be eliminated by enabling the slope filter.
- 6. Based on characterization data on a limited number of samples, not measured during final test for production.
- 7. Excluding drift due to magnetic shock.
- 8. With low-pass filter or offset cancellation enabled.
- 9. "Self-test positive difference" is defined as: OUTPUT[mg](CTRL3 ST2, ST1 bits=01) OUTPUT[mg](CTRL3 ST2, ST1 bits=00).
- 10. Magnetic "self-test" is defined as OUTPUT[gauss](self-test enabled) OUTPUT[gauss](self-test disabled).



2.2 Temperature sensor characteristics

@ Vdd = 1.8 V, T = 25 °C unless otherwise noted $^{(b)}$.

Symbol	Parameter	Test conditions	Min.	Typ. ⁽¹⁾	Max.	Unit		
TSDr	Temperature sensor output change vs. temp.			1		digit/°C ⁽²⁾		
TODR	Temperature refresh rate			12.5		Hz		
Тор	Operating temperature range		-40		+85	°C		

Table 4. Temperature sensor characteristics

1. Typical specifications are not guaranteed.

2. 8-bit resolution.

2.3 Electrical characteristics

@ Vdd = 1.8 V, T = 25 $^{\circ}$ C unless otherwise noted. ^(b)

Table 5. Electrical characteristics

Symbol	Parameter	Test conditions	Min.	Typ. ⁽¹⁾	Max.	Unit
Vdd	Supply voltage		1.71		1.98	V
Vdd_IO	Module power supply for I/O ⁽²⁾		1.71	1.8	Vdd+0.1	V
LA_Idd_HR	Accelerometer current consumption in high-resolution mode. Magnetic sensor in power-down.	12.5Hz-6400Hz ODR range		162		μA
		100 Hz ODR		16		μA
LA Idd LP	Accelerometer current consumption in low-power mode.	50 Hz ODR		10		μA
	Magnetic sensor in power-down.	12.5 Hz ODR		6		μA
		1 Hz ODR		4.5		μA
M_ldd_HR	Magnetic current consumption in high- resolution mode. Accelerometer in power-down mode.	ODR = 20 Hz		200		μA
M_ldd_LP	Magnetic current consumption in low- power mode. Linear accel. in power-down mode.	ODR = 20 Hz		50		μA
Idd_PD	Current consumption in power-down			2.5		μA
V _{IH}	Digital high-level input voltage		0.7*Vdd_IO			V
V _{IL}	Digital low-level input voltage				0.3*Vdd_IO	V
V _{OH}	High-level output voltage	I _{OH} = 4 mA ⁽³⁾	Vdd_IO - 0.2			V
V _{OL}	Low-level output voltage	$I_{OL} = 4 \text{ mA}^{(3)}$			0.2	V
T _{OP}	Operating temperature range		-40		+85	°C

1. Typical specifications are not guaranteed.

2. It is possible to remove Vdd maintaining Vdd_IO without blocking the communication bus, in this condition the measurement chain is powered off.

3. 4 mA is the maximum driving capability, i.e. the maximum DC current that can be sourced/sunk by the digital pin in order to guarantee the correct digital output voltage levels V_{OH} and V_{OL} .

b. The product is factory calibrated at 1.8 V.The operational power supply range is from 1.71 V to 1.98 V.



2.4 Communication interface characteristics

2.4.1 SPI - serial peripheral interface

Subject to general operating conditions for Vdd and Top.

Symbol	Parameter	Valu	ue ⁽¹⁾	11:0:4
Symbol	Parameter	Min	Мах	Unit
t _{c(SPC)}	SPI clock cycle	100		ns
f _{c(SPC)}	SPI clock frequency		10	MHz
t _{su(CS)}	CS setup time	5		
t _{h(CS)}	CS hold time	20		
t _{su(SI)}	SDI input setup time	5		
t _{h(SI)}	SDI input hold time	15		ns
t _{v(SO)}	SDO valid output time		50	
t _{h(SO)}	SDO output hold time	5		
t _{dis(SO)}	SDO output disable time		50	

Table 6. SPI slave timing values

Figure 3. SPI slave timing diagram



Note:

Values are guaranteed at 10 MHz clock frequency for SPI with 3 wires, based on characterization results, not tested in production.

Measurement points are done at 0.2·Vdd_IO *and* 0.8·Vdd_IO, *for both input and output ports.*



2.4.2 I²C - inter-IC control interface

Subject to general operating conditions for Vdd and Top.

Cumhal	Parameter	I ² C standa	rd mode ⁽¹⁾	l ² C fast mode ⁽¹⁾		11
Symbol	Parameter	Min	Max	Min	Max	Unit
f _(SCL)	SCL clock frequency	0	100	0	400	kHz
t _{w(SCLL)}	Low period of the SCL clock	4.7		1.3		
t _{w(SCLH)}	High period of the SCL clock	4.0		0.6		- µs
t _{su(SDA)}	Data setup time	250		100		ns
t _{h(SDA)}	Data hold time	0	3.45	0	0.9	
t _{h(ST)}	START condition hold time	4		0.6]
t _{su(SR)}	Setup time for a repeated START condition	4.7		0.6		μs
t _{su(SP)}	Setup time for STOP condition	4		0.6]
t _{w(SP:SR)}	Bus free time between STOP and START condition	4.7		1.3		

1. Data based on standard I^2C protocol requirement, not tested in production.

Symbol	Parameter	l ² C fast mode plus ⁽¹⁾		I ² C high speed ⁽¹⁾		Unit
		Min	Max	Min	Max	
f _(SCL)	SCL clock frequency	0	1	0	3.4	MHz
t _{w(SCLL)}	Low period of the SCL clock	0.5		0.16		
t _{w(SCLH)}	High period of the SCL clock	0.26		0.06		μs
t _{su(SDA)}	Data setup time	50		10		ns
t _{h(SDA)}	Data hold time	0		0	0.07	
t _{h(ST)}	START condition hold time	0.26		0.16		
t _{su(SR)}	Setup time for a repeated START condition	0.26		0.16		μs
t _{su(SP)}	Setup time for STOP condition	0.26		0.16		
t _{w(SP:SR)}	Bus free time between STOP and START condition	0.5				

Table 8. I²C slave timing values (fast mode plus and high speed)

1. Data based on standard l^2C protocol requirement, not tested in production.









2.5 Absolute maximum ratings

Stresses above those listed as "absolute maximum ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device under these conditions is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Symbol	Ratings	Maximum value	Unit
Vdd	Supply voltage	-0.3 to 2.2	V
Vdd_IO	I/O pins supply voltage	-0.3 to 2.2	V
Vin	Input voltage on any control pin (CS, SCL/SPC, SDA/SDI/SDO)	-0.3 to Vdd_IO +0.3	V
Δ	Acceleration (any axis, powered, Vdd = 1.8 V)	3000 for 0.5 ms	g
A _{POW}	Acceleration (any axis, powered, vul – 1.6 v)	10000 for 0.2 ms	g
	Acceleration (any axis, unpowered)	3000 for 0.5 ms	g
A _{UNP}	Acceleration (any axis, unpowered)	10000 for 0.2 ms	g
M _{EF}	Maximum exposed field	10000	gauss
T _{OP}	Operating temperature range	-40 to +85	°C
T _{STG}	Storage temperature range	-40 to +125	°C
ESD	Electrostatic discharge protection (HBM)	2	kV

Table 9. Absolute maximum ratings

Note:

Supply voltage on any pin should never exceed 2.2 V.



This device is sensitive to mechanical shock, improper handling can cause permanent damage to the part.



This device is sensitive to electrostatic discharge (ESD), improper handling can cause permanent damage to the part.



3 Terminology

3.1 Sensitivity

3.1.1 Linear acceleration sensor sensitivity

Sensitivity describes the gain of the sensor and can be determined by applying 1 g acceleration to it. As the sensor can measure DC accelerations this can be done easily by pointing the axis of interest towards the center of the Earth, noting the output value, rotating the sensor by 180 degrees (pointing to the sky) and noting the output value again. By doing so, $\pm 1 g$ acceleration is applied to the sensor. Subtracting the larger output value from the smaller one, and dividing the result by 2, leads to the actual sensitivity of the sensor. This value changes very little over temperature and time. The sensitivity tolerance describes the range of sensitivities of a large population of sensors.

3.1.2 Magnetic sensor sensitivity

Sensitivity describes the ratio of the output digital data expressed in LSB units and the applied magnetic field expressed in mG (milligauss). It can be measured, for example, by applying a known magnetic field along one axis and measuring the digital output of the device.

3.2 Zero-g level

The zero-*g* level offset (LA_TyOff) describes the deviation of an actual output signal from the ideal output signal if no acceleration is present. A sensor in a steady state on a horizontal surface will measure 0 *g* on the X-axis and 0 *g* on the Y-axis whereas the Z-axis will measure 1 *g*. The output is ideally in the middle of the dynamic range of the sensor (content of OUT registers 00h, data expressed as two's complement number). A deviation from the ideal value in this case is called zero-*g* offset. Offset is to some extent a result of stress to MEMS sensor and therefore the offset can slightly change after mounting the sensor onto a printed circuit board or exposing it to extensive mechanical stress. Offset changes little with temperature, see *Table 3* "Zero-*g* level change vs. temperature" (LA_TCOff). The zero-*g* level tolerance (TyOff) describes the standard deviation of the range of zero-*g* levels of a population of sensors.

3.3 Zero-gauss level

Zero-gauss level offset (M_TyOff) describes the deviation of an actual output signal from the ideal output if no magnetic field is present.

3.4 Magnetic dynamic range

The magnetic dynamic range is defined as the magnetic field driven along one sensitive axis, giving the maximum digital output value.

20/82



4 Functionality

4.1 Magnetometer

4.1.1 Magnetometer power modes

The LSM303AH magnetometer provides two different power modes: high-resolution and low-power modes.

The tables below summarize the magnetometer RMS noise values and current consumption in different product configurations.

When the low-pass filter is enabled, the bandwidth is reduced while noise performance is improved without any increase in power consumption.

CFG_REG_B_M[LPF] or	(CFG_REG_A_M [LP = 0]) high-resolution mode		(CFG_REG_A_M [LP = 1]) low-power mode	
CFG_REG_B_M[OFF_CANC]	BW [Hz]	Noise RMS [mg]	BW [Hz]	Noise RMS [mg]
0 (disable)	ODR/2	4.5	ODR/2	9
1 (enable)	ODR/4	3	ODR/4	6

Table 10. RMS noise of operating modes

Table 11. Current consumption of operating modes

ODR (Hz)	Current consumption (µA) (CFG_REG_A_M [LP] = 0) high-resolution CFG_REG_B_M [OFF_CANC] = 0	Current consumption (µA) (CFG_REG_A_M [LP] = 1) low-power CFG_REG_B_M [OFF_CANC] = 0	Current consumption (µA) (CFG_REG_A_M [LP] = 0) high-resolution CFG_REG_B_M [OFF_CANC] = 1	Current consumption (µA) (CFG_REG_A_M [LP] = 1) low-power CFG_REG_B_M [OFF_CANC] = 1
10	100	25	125	55
20	200	50	240	105
50	475	125	590	255
100	950	250	1180	505



The following table summarizes the turn-on time of the magnetometer in the two different power modes with the offset cancellation function enabled or disabled (see Section 4.1.2: Magnetometer offset cancellation).

Operating mode	Turn-on time				
CFG_REG_A_M[LP]	P] CFG_REG_A_M[OFF_CANC = 0] CFG_REG_A_M[OFF_CAN				
0 (high-resolution)	9.4 ms 9.4 ms + 1/ODR				
1 (low-power)	6.4 ms 6.4 ms + 1/ODR				

Table 12. Operating mode and turn-on time

The LSM303AH offers single measurement mode in both high-resolution and low-power modes.

Single measurement mode is enabled by writing bits MD[1:0] to '01' in *CFG_REG_A_M* (60h).

In single measurement mode, once the measurement has been performed, the DRDY pin is set to high, data is available in the output register and the LSM303AH is automatically configured in idle mode by setting the MD[1] bit to '1'.

Single measurement is independent of the programmed ODR but depends on the frequency at which the MD[1:0] bits are written by the microcontroller/application processor.

Maximum ODR frequency achievable in single mode measurement is given in the following table.

Maximum ODR	Power mode (CFG_REG_A_M[LP])
100 Hz	High resolution (LP = '0')
150 Hz	Low power (LP = '1')

Table 13. Maximum ODR in single measurement mode (HR and LP modes)

In single measurement mode, for ODR < 10 Hz, current consumption can be calculated with the following formula:

(Current_consumption_10Hz - Current_consumption_in_power_down) / (10 Hz / ODR) + Current_consumption_in_power_down

Where Current_consumption_in_power_down and Current_consumption_10Hz can be found, respectively, in *Table 5* and *Table 11*.



4.1.2 Magnetometer offset cancellation

Offset cancellation is the result of performing a set and reset in the magnetic sensor.

The offset cancellation technique is defined as follows:

$$H_{out} = \frac{H_n + H_{n-1}}{2}$$

where H_n and H_{n-1} are two consecutive magnetic field measurements, one after a set pulse, the other after a reset pulse.

Considering a magnetic offset (Hoff), the two magnetic field measurements are:

- Set: H_n = H + H_{off}
- Reset: H_{n-1} = H H_{off}

The offset is cancelled according to the offset cancellation technique:

$$H_{out} = \frac{H_n + H_{n-1}}{2} = \frac{2H + H_{off} - H_{off}}{2} = H$$

In the LSM303AH offset cancellation is enabled by setting bit OFF_CANC = 1 (and bit OFF_CANC_ONE_SHOT = 1 in single measurement mode) in $CFG_REG_B_M$ (61h).

Offset cancellation is automatically managed by the device in continuous mode.

Offset cancellation has to be managed by the user in single measurement mode averaging two consecutive measurements H_n and H_{n-1} .

If offset cancellation is disabled, a set of the magnetic sensor is performed anyway.

The set pulse frequency can be configured by setting the Set_FREQ bit in *CFG_REG_B_M* (61h).

4.1.3 Magnetometer interrupt

In LSM303AH magnetometer interrupt signal generation is based on the comparison between data and a programmable threshold.

To enable the interrupt function, in INT_CTRL_REG_M register (63h) the "IEN" bit must be set to '1'.

In the LSM303AH the user can select the axis/axes in which the interrupt function can be enabled. In order to do this, the XIEN, YIEN, and ZIEN bits in *INT_CTRL_REG_M (63h)* need be set properly.

The threshold value can be programmed by setting the *INT_THS_L_REG_M* (65h) and *INT_THS_H_REG_M* (66h) registers.

The threshold is expressed in absolute value as a 15-bit unsigned number. The threshold has the same sensitivity as the magnetic data.

When magnetic data exceeds the positive or the negative threshold, the interrupt signal is generated and the information about the type of interrupt is stored in the *INT_SOURCE_REG_M (64h)* register. In particular, when magnetic data exceeds the positive threshold the P_TH_S_axis bit is set to '1', while if data exceeds the negative threshold the N_TH_S_axis bit is set to '1'. If magnetic data lay between the positive and the negative thresholds, no interrupt signal is released.





Figure 5. Interrupt function

Two different approaches for the interrupt function are available:

- Typical: comparison is between magnetic data read by the sensor and the programmable threshold;
- Advanced: comparison is made between magnetic data after hard-iron correction and the programmable threshold.

These approaches are configurable by setting the INT_on_DataOFF bit in *CFG_REG_B_M* (61h).

If INT_on_DataOFF is set to '0' the typical approach is selected, otherwise if it is set to '1' the advanced approach is selected.

Two different interrupts are available:

- Pulsed interrupt signal: it goes high when the magnetic data exceed one of the two thresholds and goes low when the magnetic data are between the two thresholds. This kind of interrupt is selected by setting the IEL bit in *INT_CTRL_REG_M (63h)* to '0'.
- Latched interrupt signal: it goes high when the data exceed one of the two thresholds but is reset only once the source register is read and not when the magnetic data returns between the two thresholds. This kind of interrupt is selected by setting the IEL bit in *INT_CTRL_REG_M (63h)* to '1'.

The interrupt signal polarity can be set using the IEA bit in INT_CTRL_REG_M (63h).

If IEA is set to '1' then the interrupt signal is active high, while if it is set to '0' the interrupt signal is active low.

In order to drive the interrupt signal from the DRDY pad, the INT_MAG_PIN bit in *CFG_REG_C_M (62h)* must be set to '1'.



4.1.4 Magnetometer hard-iron compensation

Hard-iron distortion occurs when a magnetic object is placed near the magnetometer and appears as a permanent bias in the sensor's outputs.

The hard-iron correction consists of compensating magnetic data from hard-iron distortion.

The operation is defined as follows:

 $H_{out} = H_{read} - H_{HI}$

where:

- H_{read} is the generic uncompensated magnetic field data, as read by the sensor;
- H_{HI} is the hard-iron distortion field;
- H_{out} is the compensated magnetic data.

The computation of the hard-iron distortion field should be performed by an external processor. After the computation of the hard iron-distortion field has been performed, the measured magnetic data can be compensated.

The LSM303AH offers the possibility of storing hard-iron data inside six dedicated registers from 45h to 4Ah.

Each register contains eight bits so that the hard-iron data can be expressed as a 16-bit two's complement number. The OFFSET_axis_REG_H registers contain the MSBs of the hard-iron data, while the OFFSET_axis_REG_L registers contain the LSBs.

Hard-iron data have the same format and weight of the magnetic output data. The hard-iron values stored in dedicated registers are automatically subtracted from the output data.

4.1.5 Magnetometer self-test

The self-test function is available for the magnetic sensor. When the magnetic self-test is enabled, a current is forced into a coil inside the device. This current will generate a magnetic field that will produce a variation of the magnetometer output signals. If the output signals change within the amplitude limits specified in *Table 3* then the sensor is working properly and the parameters of the interface chip are within the defined specifications.

The self-test procedure is described in the following figure.





Figure 6. Magnetometer self-test procedure





4.2 Accelerometer

4.2.1 Accelerometer power modes

The LSM303AH accelerometer provides two different power modes: high-resolution (including high-frequency mode) and low-power modes.

The following tables summarize the selection of the different operating modes as well as the low-pass filter and current consumption.

CTRL1_A(ODR[3:1])	CTRL1_A(HF_ODR)	ODR selection [Hz]	Bit resolution	Mode	
Accelerometer low-po	ower mode				
0000	-	-	-	PD	
1000	-	1			
1001	-	12.5			
1010	-	25			
1011	-	50	10	LP	
1100	-	100	10	LF	
1101	-	200			
1110	-	400			
1111	-	800			
Accelerometer high-r	esolution mode				
0001	-	12.5			
0010	-	25			
0011	-	50			
0100	-	100	14	HR	
0101	0	200			
0110	0	400			
0111	0	800			
0101	1	1600			
0110	1	3200	12 1	HF	
0111	1	6400			



57

ODR [Hz]	LPF cutoff [Hz]		
Low-power mode			
800	-		
400			
200	-		
100	3200		
50			
25			
12.5			
1			
High-resolution mode			
800	355		
400	177		
200	88		
100	44		
50	22		
25	11		
12.5	5.5		
High-frequency mode			
6400	2840		
3200	1420		
1600	710		

Table 15. Low-pass filter in low-power, high-resolution and high-frequency modes

Table 16. Current consumption of operating modes

ODR (Hz)	Typical current consumption in high-resolution/high-frequency mode [µA]	Typical current consumption in low-power mode [μΑ]
1	-	4.5
12.5	162	6
25		7.5
50		10
100		16
200		26.5
400		48.5
800		92.5
1600		
3200		
6400		

4.2.2 Accelerometer 6D / 4D orientation detection

The LSM303AH includes 6D / 4D orientation detection which applies only to the accelerometer.

In this configuration the interrupt is generated when the device is stable in a known direction. In 4D configuration, detection of the position of the Z-axis is disabled.

4.2.3 Accelerometer activity/inactivity function

The Activity/Inactivity recognition function allows reducing the power consumption of the system in order to develop new smart applications and is applicable only to the accelerometer block of the device.

When the Activity/Inactivity recognition function is activated, the LSM303AH is able to automatically go to 12.5 Hz sampling rate and to wake up as soon as the interrupt event has been detected, increasing the output data rate and bandwidth.

With this feature the system may be efficiently switched from low-power mode to full performance depending on user-selectable positioning and acceleration events, thus ensuring power saving and flexibility.

The Activity/Inactivity recognition function is activated by writing the desired threshold in the *WAKE_UP_THS_A (33h)* register. The high-pass filter is automatically enabled.

If the device is in Sleep (Inactivity) mode, when at least one of the axes exceeds the threshold in the *WAKE_UP_THS_A (33h)* the device goes into Sleep-to-Wake (as Wake-Up).

Activity/Inactivity threshold and duration can be configured in the control registers:

WAKE_UP_THS_A (33h) WAKE_UP_DUR_A (34h)

4.2.4 Accelerometer self-test

The self-test allows the user to check the sensor functionality without moving it. When the self-test is enabled, an actuation force is applied to the sensor, simulating a definite input acceleration. In this case the sensor outputs will exhibit a change in their DC levels which are related to the selected full scale through the device sensitivity. When the self-test is activated, the device output level is given by the algebraic sum of the signals produced by the acceleration acting on the sensor and by the electrostatic test-force. If the output signals change within the amplitude specified inside *Table 3*, then the sensor is working properly and the parameters of the interface chip are within the defined specifications.

The self-test procedure is described in the following figure.





Figure 7. Accelerometer self-test procedure





4.2.5 Accelerometer data stabilization time vs. ODR setting

The data stabilization time required when an ODR change is applied in order to have valid usable data depends on the ODR selected and accelerometer setting.

The table below provides the number of samples to be discarded in order to obtain valid usable data for the accelerometer.

ODR [Hz]	HF	HR	LP
6400	6	-	-
3200	2	-	-
1600	1	-	-
800	-	1	0
400	-	1	0
200	-	1	0
100	-	1	0
50	-	0	0
25	-	0	0
12.5	-	0	0
1	-	-	0

Table 17. Number of samples to be discarded

4.2.6 Accelerometer anti-aliasing filter

The anti-aliasing filter reveals a robustness against external signal disturbance, maintaining the best accelerometer signal integrity.

The anti-aliasing bandwidth has a bandwidth of ODR/2 in high-resolution (HR) and high-frequency (HF) modes. Refer to *Table 15* for additional details on filtering.

4.3 IC interface

The complete measurement chain is composed of a low-noise capacitive amplifier which converts the capacitive unbalancing of the MEMS sensor into an analog voltage using an analog-to-digital converter.

The acceleration and magnetic data may be accessed through an I²C/SPI interface, thus making the device particularly suitable for direct interfacing with a microcontroller.

The LSM303AH features a data-ready signal which indicates when new sets of measured acceleration and magnetic data are available, thus simplifying data synchronization in the digital system that uses the device.



4.4 FIFO

The FIFO buffer applies only to the accelerometer. The LSM303AH embeds 256 slots of 14-bit data FIFO for each of the three output channels, X, Y and Z of the acceleration module. This allows consistent power saving for the system, since the host processor does not need to continuously poll data from the sensor, but it can wake up only when needed and burst the significant data out from the FIFO.

The internal FIFO allows collecting 256 samples (14-bit size data) for each axis or storing the output of the module computation up to 768 samples (14-bit size data).

This buffer can work according to the following 5 different modes:

- Bypass mode
- FIFO mode
- Continuous-to-FIFO
- Bypass-to-Continuous
- Continuous

Each mode is selected by the FIFO_MODE bits in the FIFO_CTRL_A (25h) register.

Programmable FIFO threshold status, FIFO overrun events and the number of unread samples stored are available in the *FIFO_SRC_A (2Fh)* and *FIFO_SAMPLES_A (30h)* registers and can be set to generate dedicated interrupts on the INT1 and INT2 pins using the *CTRL4_A (23h)* and *CTRL5_A (24h)* registers.

FIFO_SRC_A (2Fh) (FIFO_FTH) goes to '1' when the number of unread samples *FIFO_SRC_A (2Fh)* and *FIFO_SAMPLES_A (30h)* (Diff[8:0]) is greater than or equal to FTH [7:0] in *FIFO_THS_A (2Eh)*.

If FTH [7:0] is equal to '0', FIFO_SRC_A (2Fh) (FIFO_FTH) goes to '0'.

FIFO_SRC_A (2Fh) (FIFO_OVRN) is equal to '1' if a FIFO slot is overwritten.

FIFO_SRC_A (2Fh) and *FIFO_SAMPLES_A (30h)* (Diff[8:0]) contain stored data levels of unread samples. When Diff[8:0] is equal to '00000000', FIFO is empty. When Diff[8:0] is equal to '100000000', FIFO is full and the unread samples are 256.

To guarantee the correct acquisition of data during the switching into and out of FIFO mode, the first sample acquired must be discarded.

When the FIFO threshold status flag is '0'-logic, FIFO filling is lower than the threshold level and when '1'-logic, FIFO filling is equal to or higher than the threshold level.

4.4.1 Bypass mode

In Bypass mode (*FIFO_CTRL_A (25h)* (FMODE [2:0])= 000), the FIFO is not operational, no data is collected in FIFO memory, and it remains empty with the only actual sample available in the output registers.

Bypass mode is also used to reset the FIFO when in FIFO mode.

For each channel only the first address is used. When new data is available, the old data is overwritten.



4.4.2 FIFO mode

In FIFO mode (*FIFO_CTRL_A (25h)* (FMODE [2:0])= 001) data from the X, Y and Z channels are stored in the FIFO until it is full, when 256 unread samples are stored in memory, data collecting is stopped.

To reset the FIFO content, Bypass mode should be written in the *FIFO_CTRL_A (25h)* register, setting the FMODE [2:0] bits to '000'. After this reset command, it is possible to restart FIFO mode, writing the value '001' in *FIFO_CTRL_A (25h)* (FMODE [2:0]).

The FIFO buffer can memorize 256 slots of X, Y and Z data.

4.4.3 Continuous mode

Continuous mode (*FIFO_CTRL_A (25h)* (FMODE[2:0] = 110) provides a continuous FIFO update: when 256 unread samples are stored in memory, as new data arrives the oldest data is discarded and overwritten by the newer.

A FIFO threshold flag *FIFO_CTRL_A (25h)* (FIFO_FTH) is asserted when the number of unread samples in FIFO is greater than or equal to *FIFO_THS_A (2Eh)* (FTH[7:0]).

It is possible to route *FIFO_CTRL_A (25h)*(FTH) to the INT1 pin by writing the INT1_FTH bit to '1' in register *CTRL4_A (23h)* or to the INT2 pin by writing the INT2_FTH bit to '1' in register *CTRL5_A (24h)*.

If an overrun occurs, the oldest sample in FIFO is overwritten and the FIFO_OVR flag in *FIFO_SRC_A (2Fh)* is asserted.

In order to empty the FIFO before it is full, it is also possible to pull from FIFO the number of unread samples available in *FIFO_SRC_A (2Fh)* and *FIFO_SAMPLES_A (30h)* (Diff[8:0]).

4.4.4 Continuous-to-FIFO mode

In Continuous-to-FIFO mode *FIFO_CTRL_A (25h)* (FMODE [2:0] = 011), FIFO operates in Continuous mode and FIFO mode starts upon an internal trigger event. When the FIFO is full, data collecting is stopped.











34/82



4.4.5 Bypass-to-Continuous mode

In Bypass-to-Continuous mode (*FIFO_CTRL_A (25h)*(FMODE[2:0] = '100'), data measurement storage inside FIFO starts in Continuous mode upon an internal trigger event, then the sample that follows the trigger is available in FIFO.



Figure 10. Bypass-to-Continuous mode

Figure 11. Trigger event to FIFO for Bypass-to-Continuous mode





4.4.6 Module-to-FIFO

When the MODULE_TO_FIFO bit in the *FIFO_CTRL_A* (25*h*) register is set to '1', the 14-bit magnitude of the vector of the current axes is sent as FIFO input instead of axes data. X-, Y- and Z-axis data are replaced with 3 times the adjacent data generated by the module routine, as shown in *Figure 12*, so a row of FIFO is written every 3 axes data ready.

The module routine must be previously enabled by writing to the *FUNC_CTRL_A (3Fh)* register.

The module data in FIFO can be read as output data in the registers 28h-2Dh.

The LSM303AH calculates the vector sum of the acceleration of the X-, Y-, Z-axis using the following formula:

module (14-bit) = Sqrt($x^2+y^2+z^2$)

The implementation is based on an approximation of this formula (error below noise level).

As shown in *Figure 12*, when module-to-FIFO is enabled, each row of FIFO contains 3 values of the module, related to 3 consecutive ODR.



Figure 12. Module-to-FIFO mode example

4.5 Embedded functions

The LSM303AH embeds internal logic able to implement the following functions which are applicable to the accelerometer only:

- Step detector
- Step counter
- Significant motion function
- Tilt function

Pedometer, significant motion, and tilt functions can work in parallel. Step detector, step counter, tilt function, and significant motion function work at 25 Hz, so the user can configure ODR at 25 Hz or higher.

	Pedometer	Tilt function	Event recognition
ODR ≥ 1600 Hz	Y	Y	Х
ODR < 1600 Hz	Y	Y	Y
ODR 25-50 Hz	Y	Y	Y
ODR 12.5 Hz	Х	Х	Y

Table 18. ODR function settings




4.5.1 Step detector/Step counter

The step detector function generates an interrupt when a step is recognized, the step counter (automatically enabled when step detector is on) counts the number of the steps detected.

Step Detector/Step Counter (SD/SC) are enabled by setting to '1'-logic the STEP_CNT_ON bit in the *FUNC_CTRL_A* (*3Fh*) register. Additional pedometer advanced configurations can be used if the FUNC_CFG_EN bit in *CTRL2_A* (*21h*) is set to "1". Details of the pedometer advanced configuration registers are available in *Section 9: Advanced configuration register mapping* and *Section 10: Advanced configuration registers description*.

To disable the pedometer advanced configurations, the FUNC_CFG_EN bit in CTRL2 (3Fh) must be set to '0'. Refer to *Section 10.4: CTRL2_A (3Fh)*.

The "step detected" interrupt can be read in the *FUNC_CK_GATE_A* (*3Dh*) register and by writing the INT2 STEP DET bit to '1'-logic in the *CTRL5_A* (*24h*) register it can be routed on INT2. The number of steps detected can be read from *STEP_COUNTER_L_A* (*3Bh*) and *STEP_COUNTER_H_A* (*3Ch*) registers (65535 steps max).

- As default, SD/SC operates with data scaled at 2 g of full scale (device full-scale independent), but it is possible to make it work with a FS of 4 g by setting the PEDO4g bit to '1'-logic.
- The number of steps can be reset by writing the bit RST nSTEP to '1'-logic in <u>STEP_COUNTER_MINTHS_A</u> (3Ah): this is a synchronous reset activated at the first data valid and before the algorithm execution. The bit is auto-reset once the counter has been successfully set to 0000h.

Note: This bit does not reset the algorithm and its variables.

The algorithm and its variables can be reset just by writing the STEP_CNT_ON bit to '0'-logic, i.e. turning off the SD/SC routine. The RST PEDO bit in the *FUNC_CK_GATE_A* (*3Dh*) register signals that a SD/SC reset has to be done, so it goes high and remains at '1'-logic value until the algorithm ends the reset procedure, which is carried out at first execution after the SD/SC routine has been re-enabled, before the algorithm starts.

4.5.2 Significant motion

The significant motion functionality can be used in location-based applications in order to receive a notification indicating when the user is changing location. This function has been implemented in hardware using only the accelerometer and works at 25 Hz, so the accelerometer ODR must be set at 25 Hz or higher values.

The significant motion interrupt signal can be driven to the interrupt pin by setting to 1 the INT2_SIG_MOT bit of the *CTRL5_A* (24h) register; it can also be checked by reading the SIG_MOT_DET bit of the *FUNC_CK_GATE_A* (3Dh) register.

The significant motion function generates an interrupt when the difference between the number of steps from its initialization is higher or equal than a threshold. The threshold value corresponds to the number of steps to be performed by the user upon a change of location before the significant motion interrupt is generated.

The threshold has a default value equal to 6. This threshold is configurable in the *SM_THS_A (34h)* register in the advanced configuration registers (refer to *Section 9: Advanced configuration register mapping* and *Section 10: Advanced configuration registers description*). The significant motion threshold can be used if the FUNC_CFG_EN bit in *CTRL2_A (21h)* is set to "1".



4.6 Factory calibration

The IC interface is factory calibrated for sensitivity (LA_So, M_GN), Zero-*g* level (LA_TyOff) and Zero-*gauss* level (M_TyOff).

The trim values are stored inside the device in nonvolatile memory. Anytime the device is turned on, the trim parameters are downloaded into the registers to be used during active operation. This allows using the device without further calibration.

38/82



5 Application hints



Figure 13. LSM303AH electrical connections

The device core is supplied through the Vdd line while the I/O pads are supplied through the Vdd_IO line. Power supply decoupling capacitors (100 nF ceramic, 10 μ F aluminum) should be placed as near as possible to pin 9 of the device (common design practice).

It is possible to remove Vdd, maintaining Vdd_IO, without blocking the communication bus, in this condition the measurement chain is powered off.

The following recommendations apply to capacitor C1:

- It must be connected as close as possible to pins 5 and 6 since very high current pulses flow from C1 to pin 5 and 6. This avoid problems caused by inductive effects due to the length of the copper strips.
- It is highly recommended to use low ESR (max 200 mOhm)

The functionality of the device and the measured acceleration data are selectable and accessible through the I^2C or SPI interfaces. When using the I^2C , CS must be tied high (i.e. connected to Vdd_IO).

The functions, the threshold and the timing of the three interrupt pins (INT1_XL, INT2_XL, and INT_MAG/DRDY) can be completely programmed by the user through the I^2C/SPI interface.



Pin#	Name	Function	Status
1	SCL SPC	I ² C serial clock (SCL) SPI serial port clock (SPC)	Default: input without pull-up
2	CS	SPI enable I ² C/SPI mode selection 1: SPI idle mode / I ² C communication enabled; 0: SPI communication mode / I ² C disabled	Default: input without pull-up
3	Reserved	Reserved, connected to GND	
4	SDA SDI SDO	I ² C serial data (SDA) SPI serial data input (SDI) 3-wire interface serial data output (SDO)	Default: (SDA) input without pull-up
5	C1	Capacitor connection (C1 = 220 nF)	External cap, voltage forced by the device
6	GND	0 V	
7	INT_MAG/DRDY	Magnetometer interrupt/data-ready signal	Default: output high impedance
8	GND	0 V	
9	Vdd	Power supply	
10	Vdd_IO	Power supply for I/O pins	
11	INT2_XL	Accelerometer interrupt 2	Default: output forced to ground
12	INT1_XL	Accelerometer interrupt 1	Default: output forced to ground

Table	19.	Pin	status
Iabio			oluluo

Note: In order to program INT_MAG/DRDY as a push-pull output, write the INT_MAG bit to 1 in CFG_REG_C_M (62h).

5.1 Soldering information

The LGA package is compliant with the ECOPACK[®], RoHS and "Green" standards. It is qualified for soldering heat resistance according to JEDEC J-STD-020.

Leave "Pin 1 Indicator" unconnected during soldering.

Land pattern and soldering recommendations are available at <u>www.st.com</u>.

5.2 High-current wiring effects

High current in wiring and printed circuit traces can be culprits in causing errors in magnetic field measurements for compassing.

Conductor-generated magnetic fields will add to the Earth's magnetic field, leading to errors in compass heading computation.

Keep currents higher than 10 mA a few millimeters away from the sensor IC.



6 Digital interfaces

The registers embedded inside the LSM303AH may be accessed through both the I^2C and SPI serial interfaces. The latter may be SW-configured to operate in 3-wire interface mode.

The serial interfaces are mapped to the same pins. To select/exploit the I^2C interface, the CS line must be tied high (i.e. connected to Vdd_IO).

Pin name	Pin description
CS	SPI enable I^2C/SPI mode selection (1: SPI idle mode / I^2C communication enabled; 0: SPI communication mode / I^2C disabled)
SCL	I ² C serial clock (SCL)
SPC	SPI serial port clock (SPC)
SDA	I ² C serial data (SDA)
SDI	SPI serial data input (SDI)
SDO	3-wire interface serial data output (SDO)

6.1 I²C serial interface

The LSM303AH I^2C is a bus slave. The I^2C is employed to write data into registers whose content can also be read back.

The relevant I²C terminology is given in the table below.

Table 2	21. I ² C	termin	ology
---------	----------------------	--------	-------

Term	Description
Transmitter	The device which sends data to the bus
Receiver	The device which receives data from the bus
Master	The device which initiates a transfer, generates clock signals and terminates a transfer
Slave	The device addressed by the master

There are two signals associated with the I²C bus: the serial clock line (SCL) and the serial data line (SDA). The latter is a bidirectional line used for sending and receiving the data to/from the interface. Both the lines must be connected to Vdd_IO through an external pull-up resistor. When the bus is free, both the lines are high.

The I²C interface is compliant with fast mode (400 kHz) I²C standards as well as with the normal mode.



6.1.1 I²C operation

The transaction on the bus is started through a START (ST) signal. A START condition is defined as a high-to-low transition on the data line while the SCL line is held high. After this has been transmitted by the master, the bus is considered busy. The next byte of data transmitted after the start condition contains the address of the slave in the first 7 bits and the eighth bit tells whether the master is receiving data from the slave or transmitting data to the slave. When an address is sent, each device in the system compares the first seven bits after a start condition with its address. If they match, the device considers itself addressed by the master.

Data transfer with acknowledge is mandatory. The transmitter must release the SDA line during the acknowledge pulse. The receiver must then pull the data line LOW so that it remains stable low during the high period of the acknowledge clock pulse. A receiver which has been addressed is obliged to generate an acknowledge after each byte of data received.

The I²C embedded inside the magnetometer block of the LSM303AH behaves like a slave device and the following protocol must be adhered to. After the start condition (ST) a slave address is sent, once a slave acknowledge (SAK) has been returned, an 8-bit sub-address (SUB) is transmitted: the 7 LSb represent the actual register address.

The I²C embedded inside the accelerometer block of the LSM303AH behaves like a slave device and the following protocol must be adhered to. After the start condition (ST) a slave address is sent. Once a slave acknowledge (SAK) has been returned, an 8-bit sub-address (SUB) is transmitted: the 7 LSb represent the actual register address while the IF_ADD_INC bit in *CTRL2_A* (21h) defines the increase in the address.

The slave address is completed with a Read/Write bit. If the bit was '1' (Read), a repeated START (SR) condition must be issued after the two sub-address bytes; if the bit is '0' (Write) the master will transmit to the slave with direction unchanged. *Table 26* explains how the SAD+read/write bit pattern is composed, listing all the possible configurations.

Mast	er	ST	SAD + W		SUB		DATA		SP	
Slav	е			SAK		SAK		SAK		

Table 22. Transfer when master is writing one byte to slave

Table 20. Transfer when master is writing mattiple sytes to slave										
Master	ST	SAD + W		SUB		DATA		DATA		SP
Slave			SAK		SAK		SAK		SAK	

Table 23. Transfer when master is writing multiple bytes to slave

Table 24. Transfer when master is receiving (reading) one byte of data from slave

Master	ST	SAD + W		SUB		SR	SAD + R			NMAK	SP
Slave			SAK		SAK			SAK	DATA		



			_					•		-	-		-		
Master	ST	SAD+W		SUB		SR	SAD+R			MAK		MAK		NMAK	SP
Slave			SAK		SAK			SAK	DATA		DAT A		DATA		

Table 25. Transfer when master is receiving (reading) multiple bytes of data from slave

Data are transmitted in byte format (DATA). Each data transfer contains 8 bits. The number of bytes transferred per transfer is unlimited. Data is transferred with the Most Significant bit (MSb) first. If a receiver can't receive another complete byte of data until it has performed some other function, it can hold the clock line SCL low to force the transmitter into a wait state. Data transfer only continues when the receiver is ready for another byte and releases the data line. If a slave receiver doesn't acknowledge the slave address (i.e. it is not able to receive because it is performing some real-time function) the data line must be left high by the slave. The master can then abort the transfer. A low-to-high transition on the SDA line while the SCL line is high is defined as a STOP condition. Each data transfer must be terminated by the generation of a STOP (SP) condition.

In the presented communication format MAK is Master acknowledge and NMAK is No Master Acknowledge.

Default address:

The accelerometer sensor slave address is 0011101b while magnetic sensor slave address is 0011110b.

The slave addresses are completed with a Read/Write bit. If the bit was '1' (Read), a repeated START (SR) condition must be issued after the two sub-address bytes. If the bit is '0' (Write) the master will transmit to the slave with direction unchanged. *Table 26* and *Table 27* explain how the SAD+Read/Write bit patterns are composed, listing all the possible configurations.

Linear acceleration sensor: the default (factory setting) 7-bit slave address is 0011101b.

Command	SAD[6:0]	R/W	SAD+R/W
Read	0011101	1	00111011
Write	0011101	0	00111010

Table 26. SAD+Read/Write patterns

Magnetic field sensor: the default (factory setting) 7-bit slave address is 0011110b.

Table 27. SAD + Read/Write patterns

Command	SAD[6:0]	R/W	SAD + R/W
Read	0011110	1	00111101 (3Dh)
Write	0011110	0	00111100 (3Ch)



6.2 SPI bus interface

The LSM303AH SPI is a bus slave. The SPI allows writing to and reading from the registers of the device.

The serial interface interacts with the application using 3 wires: **CS**, **SPC**, **SDI** and **SDO** (refer to *Table 20*).



Figure 14. Read and write protocol

CS is the serial port enable and it is controlled by the SPI master. It goes low at the start of the transmission and goes back high at the end. **SPC** is the serial port clock and it is controlled by the SPI master. It is stopped high when **CS** is high (no transmission). **SDI** and **SDO** are respectively the serial port data input and output. Those lines are driven at the falling edge of **SPC** and should be captured at the rising edge of **SPC**.

Both the read register and write register commands are completed in 16 clock pulses or in multiples of 8 in case of multiple read/write bytes. Bit duration is the time between two falling edges of **SPC**. The first bit (bit 0) starts at the first falling edge of **SPC** after the falling edge of **CS** while the last bit (bit 15, bit 23, ...) starts at the last falling edge of SPC just before the rising edge of **CS**.

bit 0: RW bit. When 0, the data DI(7:0) is written into the device. When 1, the data DO(7:0) from the device is read. In latter case, the chip will drive **SDO** at the start of bit 8.

bit 1-7: address AD(6:0). This is the address field of the indexed register.

bit 8-15: data DI(7:0) (write mode). This is the data that is written into the device (MSb first).

bit 8-15: data DO(7:0) (read mode). This is the data that is read from the device (MSb first).

In multiple read/write commands additional blocks of 8 clock periods will be added. For the accelerometer when the *CTRL2_A* (21h) (IF_ADD_INC) bit is '0', the address used to read/write data remains the same for every block. When the *CTRL2_A* (21h) (IF_ADD_INC) bit is '1', the address used to read/write data is increased at every block.

The function and the behavior of **SDI** and **SDO** remain unchanged.



6.2.1 Accelerometer SPI write



The SPI write command is performed with 16 clock pulses. A multiple byte write command is performed by adding blocks of 8 clock pulses to the previous one.

bit 0: WRITE bit. The value is 0.

bit 1 -7: address AD(6:0). This is the address field of the indexed register.

bit 8-15: data DI(7:0) (write mode). This is the data that is written inside the device (MSb first).

bit 16-... : data DI(...-8). Additional data in multiple byte writes.

The accelerometer address auto increment is enabled by default (volatile bit IF_ADD_INC in *CTRL2_A (21h)* must be set to '0' to disable).

Figure 16. Accelerometer multiple byte SPI write protocol (2-byte example)





6.2.2 Accelerometer SPI read in 3-wire mode

3-wire mode is entered by setting the *CTRL2_A (21h)* (SPI_ENABLE) bit equal to '1' (SPI serial interface read enable).





The SPI read command is performed with 16 clock pulses:

bit 0: READ bit. The value is 1.

bit 1-7: address AD(6:0). This is the address field of the indexed register.

bit 8-15: data DO(7:0) (read mode). This is the data that is read from the device (MSb first).

A multiple read command is also available in 3-wire mode.

The accelerometer address auto increment is enabled by default (volatile bit IF_ADD_INC in *CTRL2_A (21h)* must be set to '0' to disable).

6.2.3 Magnetometer SPI write



The SPI write command is performed with 16 clock pulses. The multiple byte write command is performed by adding blocks of 8 clock pulses to the previous one.

bit 0: WRITE bit. The value is 0.

bit 1-7: address AD(6:0). This is the address field of the indexed register.

bit 8-15: data DI(7:0) (write mode). This is the data that is written inside the device (MSb first).

bit 16-... : data DI(...-8). Further data in multiple byte writes.





6.2.4 Magnetometer SPI read in 3-wire mode



The SPI read command is performed with 16 clock pulses:

bit 0: WRITE bit. The value is 0.

bit 1-7: address AD(6:0). This is the address field of the indexed register.

bit 8-15: data DO(7:0) (read mode). This is the data that is read from the device (MSb first).

The multiple read command is available in 3-wire mode.



7 Register mapping

The table given below provides a list of the 8-bit registers embedded in the device and the corresponding addresses. Registers 00h through 3Fh are dedicated to the accelerometer while registers 40h through 6Fh are dedicated to the magnetometer.

Parieter ed			• •			
Name	Type ⁽¹⁾		Register address		Comment	
		Hex	Binary	Default		
RESERVED	-	00-0B		-	RESERVED	
Module_8bit_A	R	0C	00001100	output		
RESERVED	-	0D-0E		-	RESERVED	
WHO_AM_I_A	R	0F	00001111	01000011	Who I am ID	
RESERVED	-	10-1F		-	RESERVED	
CTRL1_A	R/W	20	00100000	00000000		
CTRL2_A	R/W	21	00100001	00000100		
CTRL3_A	R/W	22	00100010	00000000	Control registers	
CTRL4_A	R/W	23	00100011	00000000		
CTRL5_A	R/W	24	00100100	00000000		
FIFO_CTRL_A	R/W	25	00100101	00000000	FIFO control reg	
OUT_T_A	R	26	00100110	output	Temp sensor output	
STATUS_A	R	27	00100111	output	Status data register	
OUT_X_L_A	R	28	00101000			
OUT_X_H_A	R	29	00101001			
OUT_Y_L_A	R	2A	00101010	outout	Output registers	
OUT_Y_H_A	R	2B	00101011	output	Output registers	
OUT_Z_L_A	R	2C	00101100			
OUT_Z_H_A	R	2D	00101101			
FIFO_THS_A	R/W	2E	00101110	00000000 FIFO register		
FIFO_SRC_A	R	2F	00101111	output	FIFO SRC	
FIFO_SAMPLES_A	R/W	30	00110000	00000000	Unread samples stored in FIFO	
TAP_6D_THS_A	R/W	31	00110001	00000000	TAP, 4D, 6D threshold	
INT_DUR_A	R/W	32	00110010	00000000	Interrupt duration	
WAKE_UP_THS_A	R/W	33	00110011	00000000	TAP/D-TAP selection, Inactivity EN, Wakeup threshold	

48/82



Table 28. Register map (continued)	Table 28.	Register map	(continued)
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		U	er map (cont			
Name	Type ⁽¹⁾	Registe	r address	Default	Comment	
		Hex	Binary			
WAKE_UP_DUR_A	R/W	34	00110100	00000000	Wakeup duration	
FREE_FALL_A	R/W	35	00110101	00000000	Free-fall config.	
STATUS_DUP_A	R	36	00110110	output	Status register	
WAKE_UP_SRC_A	R	37	00110111	output	Wakeup SRC	
TAP_SRC_A	R	38	00111000	output	TAP SRC	
6D_SRC_A	R	39	00111001	output	6D SRC	
STEP_COUNTER_ MINTHS_A	R/W	3A	00111010	00010000	STEP C config	
STEP_COUNTER_L_A	R	3B	00111011	output	Steps detected LSB	
STEP_COUNTER_H_A	R	3C	00111100	output	Steps detected MSB	
FUNC_CK_GATE_A	R	3D	00111110	output	ST FUNCTION setting	
FUNC_SRC_A	R	3E	00000100	output	FUNCTION SRC	
FUNC_CTRL_A	R/W	3F	00000100	00000000	FUNCTION CTRL	
RESERVED		40-44				
OFFSET_X_REG_L_M	R/W	45	01000101	00000000		
OFFSET_X_REG_H_M	R/W	46	01000110	00000000		
OFFSET_Y_REG_L_M	R/W	47	01000111	00000000	Magnetometer	
OFFSET_Y_REG_H_M	R/W	48	01001000	00000000	hard-iron registers	
OFFSET_Z_REG_L_M	R/W	49	01001001	00000000		
OFFSET_Z_REG_H_M	R/W	4A	01001010	00000000		
RESERVED		4B-4C				
WHO_AM_I_M	R	4F	01001111	01000000	Who I am ID	
RESERVED		50-5F				
CFG_REG_A_M	R/W	60	01100000	00000011	Magnetometer	
CFG_REG_B_M	R/W	61	01100001	00000000	configuration	
CFG_REG_C_M	R/W	62	01100010	00000000	registers	
INT_CRTL_REG_M	R/W	63	01100011	11100000	Magnotomotor	
INT_SOURCE_REG_M	R	64	01100100		Magnetometer interrupt	
INT_THS_L_REG_M	R/W	65	01100101	00000000	configuration registers	
INT_THS_H_REG_M	R/W	66	01100110	00000000	registers	
STATUS_REG_M	R	67	01100111			



News	Type ⁽¹⁾	Register	address	Defeult	0	
Name	Type	Hex	Binary	Default	Comment	
OUTX_L_REG_M	R	68	01101000	output		
OUTX_H_REG_M	R	69	01101001	output		
OUTY_L_REG_M	R	6A	01101010	output	Magnetometer	
OUTY_H_REG_M	R	6B	01101010	output	output registers	
OUTZ_L_REG_M	R	6C	01101100	output		
OUTZ_H_REG_M	R	6D	01101101	output		
RESERVED		6E-6F				

Table 28. Register map (continued)

1. R = read-only register, RW = readable/writable register

Registers marked as *Reserved* must not be changed. Writing to those registers may cause permanent damage to the device.

The content of the registers that are loaded at boot should not be changed. They contain the factory calibration values. Their content is automatically restored when the device is powered up.

50/82



8 Register description

8.1 Module_8bit_A (0Ch)

Module out value (r). This register is a read-only register.

Table 29. Module_8bit_A register

					-		
Module_7	Module_6	Module_5	Module_4	Module_3	Module_2	Module_1	Module_0

Table 30. Module_8bit_A register description

Module [7:0]	Module output value (8-bit). Default value: 0	
--------------	---	--

8.2 WHO_AM_I_A (0Fh)

Who_AM_I register (r). This register is a read-only register. Its value is fixed at 43h.

Table 31. WHO_AM_I_A register default values

0 1 0 0 0 1 1					U			
	0	1	0	0	0	0	1	1

8.3 CTRL1_A (20h)

Control register 1 (r/w)

Table 32. CTRL1_A register

ODR3	ODR2	ODR1	ODR0	FS1	FS0	HF_ODR	BDU
-	•						

Table 33. CTRL1_A register description

ODR [3:0]	Output data rate & power mode selection. Default value: 0000 (see Table 34)
FS [1:0]	Full-scale selection. Default value: 00 (00: ±2 g; 01: ±16 g; 10: ±4 g; 11: ±8 g)
HF_ODR	High-frequency ODR mode enable. Default value: 0
BDU	Block data update. Default value: 0 (0: continuous update; 1: output registers not updated until MSB and LSB read)

ODR [3:0] is used to set the power mode and ODR selection. The following table lists the bit settings for power-down mode and each available frequency.

ODR[3:0]	HF_ODR	ODR selection [Hz]	Bit resolution	Mode
0000	-	-	-	PD
1000	-	1	10	LP
1001	-	12.5	10	LP
1010	-	25	10	LP



ODR[3:0]	HF_ODR	ODR selection [Hz]	Bit resolution	Mode			
1011	-	50	10	LP			
1100	-	100	10	LP			
1101	-	200	10	LP			
1110	-	400	10	LP			
1111	-	800	10	LP			

Table 34. ODR register setting: power down (PD) and low power (LP) (continued)

Table 35. ODR register setting: high resolution (HR) and high frequencies (HF)

ODR[3:0]	HF_ODR	ODR selection [Hz]	Bit resolution	Mode
0001	-	12.5	14	HR
0010	-	25	14	HR
0011	-	50	14	HR
0100	-	100	14	HR
0101	0	200	14	HR
0110	0	400	14	HR
0111	0	800	14	HR
0101	1	1600	12	HF
0110	1	3200	12	HF
0111	1	6400	12	HF

The BDU bit is used to inhibit the update of the output registers until both upper and lower register parts are read. In default mode (BDU = '0') the output register values are updated continuously. When the BDU is activated (BDU = '1'), the content of the output registers is not updated until both MSB and LSB are read which avoids reading values related to different sample times.

8.4 CTRL2_A (21h)

Control register 2 (r/w)

Table 36. CTRL2_A register

BOOT		0 ⁽¹⁾ FUNC_ CFG_EN ⁽²⁾⁽³⁾⁽⁴⁾	FDS_ SLOPE	IF_ADD_ INC	I2C_ DISABLE	SPI_ENABLE
------	--	---	---------------	----------------	-----------------	------------

1. This bit must be set to '0' for the correct operation of the device.

- 2. When this bit is enabled, only advanced configuration registers can be written. For proper functionality of the device, all the other registers must not be modified.
- 3. Details of advanced configuration registers are available in Section 9: Advanced configuration register mapping and Section 10: Advanced configuration registers description.
- To disable the advanced configuration, bit FUNC_CFG_EN in CTRL2_A (3Fh) must be set to '0'. Refer to Section 10.4: CTRL2_A (3Fh)



	Table 37. CTRE2_A register description
воот	Reboot memory content. Default value: 0 (0: normal mode; 1: reboot memory content)
SOFT_RESET	Soft reset acts as reset for all control registers, then goes to 0. Default value: 0 (0: disabled; 1: enabled)
FUNC_ CFG_EN	Access to advanced configuration registers from address 2Bh to 3Fh. Default value: 0 (0: disable the access to advanced configuration registers; 1: enable the access to advanced configuration registers)
FDS_SLOPE	High-pass filter data selection on output register and FIFO. Default value: 0 (0: internal filter bypassed; 1: internal filter enabled on output register and FIFO)
IF_ADD_INC	Register address automatically incremented during multiple byte access with a serial interface (I ² C or SPI). Default value: 1 (0: disabled; 1: enabled)
I2C_DISABLE	Disable I ² C communication protocol. Default value: 0 (0: SPI and I ² C interfaces enabled; 1: I ² C mode disabled)
SPI_ENABLE	3-wire SPI interface read enable. Default value: 00: SPI read disabled1: SPI read enabled

Table 37. CTRL2_A register description

8.5 CTRL3_A (22h)

Control register 3 (r/w)

Table 38. CTRL3_A register

9	T2	ST1	TAP X FN	TAP Y FN	TAP 7 FN	LIR	
		011			·/··· _2_EI		11_00

Table 39. CTRL3_A register description

ST [2:1]Self-test enable. Default value: 00 (00: Self-test disabled; Other: see Table 40)TAP_X_ENTap recognition on X direction enable. Default value: 0 (0: disabled; 1: enabled)TAP_Y_ENTap recognition on Y direction enable. Default value: 0 (0: disabled; 1: enabled)TAP_Z_ENTap recognition on Z direction enable. Default value: 0 (0: disabled; 1: enabled)TAP_Z_ENTap recognition on Z direction enable. Default value: 0 (0: disabled; 1: enabled)LIRLatched Interrupt. Switches between latched ('1'-logic) and pulsed ('0'-logic) mode for function source signals and interrupts routed to pins (wakeup, tap, double-tap, tilt, pedometer, significant motion). Default value: 0 (0: interrupt request not latched; 1: interrupt request latched)H_LACTIVEInterrupt active high, low. Default value: 0 (0: active high; 1: active low)PP_ODPush-pull/open-drain selection on interrupt pad. Default value: 0 (0: push-pull; 1: open-drain)		
TAP_Y_ENTap recognition on Y direction enable. Default value: 0 (0: disabled; 1: enabled)TAP_Z_ENTap recognition on Z direction enable. Default value: 0 (0: disabled; 1: enabled)TAP_Z_ENTap recognition on Z direction enable. Default value: 0 (0: disabled; 1: enabled)LIRLatched Interrupt. Switches between latched ('1'-logic) and pulsed ('0'-logic) mode for function source signals and interrupts routed to pins (wakeup, tap, double-tap, tilt, pedometer, significant motion). Default value: 0 (0: interrupt request not latched; 1: interrupt request latched)H_LACTIVEInterrupt active high, low. Default value: 0 (0: active high; 1: active low)PP_ODPush-pull/open-drain selection on interrupt pad. Default value: 0	ST [2:1]	
TAP_Z_ENTap recognition on Z direction enable. Default value: 0 (0: disabled; 1: enabled)LIRLatched Interrupt. Switches between latched ('1'-logic) and pulsed ('0'-logic) mode for function source signals and interrupts routed to pins (wakeup, tap, double-tap, tilt, pedometer, significant motion). Default value: 0 (0: interrupt request not latched; 1: interrupt request latched)H_LACTIVEInterrupt active high, low. Default value: 0 (0: active high; 1: active low)PP_ODPush-pull/open-drain selection on interrupt pad. Default value: 0	TAP_X_EN	
LIR Latched Interrupt. Switches between latched ('1'-logic) and pulsed ('0'-logic) mode for function source signals and interrupts routed to pins (wakeup, tap, double-tap, tilt, pedometer, significant motion). Default value: 0 (0: interrupt request not latched; 1: interrupt request latched) H_LACTIVE Interrupt active high, low. Default value: 0 (0: active high; 1: active low) PP_OD Push-pull/open-drain selection on interrupt pad. Default value: 0	TAP_Y_EN	
function source signals and interrupts routed to pins (wakeup, tap, double-tap, tilt, pedometer, significant motion). Default value: 0 (0: interrupt request not latched; 1: interrupt request latched) H_LACTIVE Interrupt active high, low. Default value: 0 (0: active high; 1: active low) PP_OD Push-pull/open-drain selection on interrupt pad. Default value: 0	TAP_Z_EN	
(0: active high; 1: active low) PP_OD Push-pull/open-drain selection on interrupt pad. Default value: 0	LIR	function source signals and interrupts routed to pins (wakeup, tap, double-tap, tilt, pedometer, significant motion). Default value: 0
	H_LACTIVE	
	PP_OD	



ST2	ST1	Self-test mode
0	0	Normal mode
0	1	Positive sign self-test
1	0	Negative sign self-test
1	1	Not allowed

Table 40. Self-test mode selection

8.6 CTRL4_A (23h)

Control register 4 (r/w): interrupt 1 configuration

Table 41. CTRL4_A register

0 ⁽¹⁾	INT1_S_ TAP	INT1_WU	INT1_FF	INT1_TAP	INT1_6D	INT1_FTH	INT1_DRDY
------------------	----------------	---------	---------	----------	---------	----------	-----------

1. This bit must be set to '0' for correct device operation.

Table 42. CTRL4_A register description

INT1_S_TAP	Single-tap recognition is routed on INT1 pad. Default value: 0 (0: disabled; 1: enabled)
INT1_WU	Wakeup recognition is routed on INT1 pad. Default value: 0 (0: disabled; 1: enabled)
INT1_FF	Free-fall recognition is routed on INT1 pad. Default value: 0 (0: disabled; 1: enabled)
INT1_TAP	Double-tap recognition is routed on INT1 pad. Default value: 0 (0: disabled; 1: enabled)
INT1_6D	6D recognition is routed on INT1 pad. Default value: 0 (0: disabled; 1: enabled)
INT1_FTH	FIFO threshold interrupt is routed on INT1 pad. Default value: 0 (0: disabled; 1: enabled)
INT1_DRDY	Data-Ready is routed on INT1 pad. Default value: 0 (0: disabled; 1: enabled)



8.7 CTRL5_A (24h)

Control register 5 (r/w): interrupt 2 configuration

Table 43. CTRL5_A register

DRDY_	INT2_	INT2_	INT2_	INT2_	INT2_	INT2_	INT2_
PULSED	BOOT	ON_INT1	TILT	SIG_MOT	STEP	FTH	DRDY

Table 44. CTRL5_A register description

DRDY_ PULSED	Data-ready interrupt mode selection: latched mode / pulsed mode. Default value: 0 (0: latched mode; 1: pulsed mode for data-ready)
INT2_BOOT	Boot state routed on INT2 pad. Default value: 0 (0: disabled; 1: enabled)
INT2_ON INT1	All signals routed on INT2 are also routed on INT1. Default value: 0 (0: disabled; 1: enabled)
INT2_TILT	Tilt event is routed on INT2 pad. Default value: 0 (0: disabled; 1: enabled)
INT2_SIG_ MOT	Significant motion detection is routed on INT2 pad. Default value: 0 (0: disabled; 1: enabled)
INT2_ STEP	Step detection is routed on INT2 pad. Default value: 0 (0: disabled; 1: enabled)
INT2_FTH	FIFO threshold interrupt is routed on INT2 pad. Default value: 0 (0: disabled; 1: enabled)
INT2_DRDY	Data-Ready is routed on INT2 pad. Default value: 0 (0: disabled; 1: enabled)



8.8 FIFO_CTRL_A (25h)

FIFO control register 5 (r/w).

Table	45.	FIFO	CTRL	Α	register

FMODE2 FMODE1 FMODE	INT2_STEP_ COUNT_OV	MODULE_ TO_FIFO	0 ⁽¹⁾	0 ⁽¹⁾	IF_CS_PU_ DIS
---------------------	------------------------	--------------------	------------------	------------------	------------------

1. This bit must be set to '0' for correct device operation.

Table 46. FIFO_CTRL_A register description

FMODE [2:0]	FIFO mode selection bits. Default: 000. For further details refer to Table 47.
INT2_STEP_ COUNT_OV	Step counter overflow interrupt enable on INT2 pad. Default value: 0 (0: disabled; 1: enabled)
MODULE_TO_ FIFO	When set to '1'-logic, module routine result is send to FIFO instead of X,Y,Z acceleration data
IF_CS_PU_DIS	When '1'-logic disconnects pull-up in if_cs pad. Default: 0

When the FIFO has been enabled, data acquired has been stored at the accelerometer ODR and the trigger signal of FIFO writing is the accelerometer internal data-ready.

FIFO data can be stored in default configuration where inertial data as been stored as X, Y, Z data or in module configuration:

Default configuration: 256-level inertial data (14-bit stored data for X, Y, Z)

User-selectable: 768 module data (14-bit each module)

FMODE2	FMODE1	FMODE0	Mode					
0	0	0	Bypass mode: FIFO turned off					
0	0	1	FIFO mode: Stops collecting data when FIFO is full.					
0	1	0	Reserved					
0	1	1	Continuous-to-FIFO: Stream mode until trigger is deasserted, then FIFO mode					
1	0	0	Bypass-to-Continuous: Bypass mode until trigger is deasserted, then FIFO mode					
1	0	1	Reserved					
1	1	0	Continuous mode: data If the FIFO is full, the new sample overwrites the older sample.					
1	1	1	Reserved					



8.9 OUT_T_A (26h)

Temperature output register (r).

		Tab	ole 48. OUT	_T_A regis	ster		
TEMP7	TEMP6	TEMP5	TEMP4	TEMP3	TEMP2	TEMP1	TEMP0

Table 49. OUT_T_A register description

Temp [7:0]	Temperature sensor output data. The value is expressed as two's complement sign. Sensitivity = 1 °C/LSB 0 LSB represents T=25 °C ambient.
	0 LOB represents 1–25° C ambient.

8.10 STATUS_A (27h)

Status register (r)

Table 50. STATUS_A register

FIFO_THS	WU_IA	SLEEP_ STATE	DOUBLE_ TAP	SINGLE_ TAP	6D_IA	FF_IA	DRDY

Table 51. STATUS_A register description

FIFO_THS	FIFO threshold status flag. (0: FIFO filling is lower than threshold level; 1: FIFO filling is equal to or higher than the threshold level.)
WU_IA	Wakeup event detection status. (0: WU event not detected; 1: Wakeup event detected)
SLEEP_ STATE	Sleep event status. (0: Sleep event not detected; 1: Sleep event detected)
DOUBLE_ TAP	Double-tap event status (0: Double-tap event not detected; 1: Double-tap event detected)
SINGLE_ TAP	Single-tap event status (0: Single-tap event not detected; 1: Single-tap event detected)
6D_IA	Source of change in position portrait/landscape/face-up/face-down. (0: no event detected; 1: a change in position detected)
FF_IA	Free-fall event detection status. (0: free-fall event not detected; 1: free-fall event detected)
DRDY	Data-ready status. (0: not ready; 1: X-, Y- and Z-axis new data available)



8.11 OUT_X_L_A (28h)

X-axis LSB output register (r)

Table 52.	OUT X	(L A	register	default values
		`_ - _/ `		

X_L7 X_L6 X_L5 ⁽²⁾ X_L4 ⁽²⁾ X_L3 ⁽¹⁾⁽²⁾ X_L2 ⁽¹⁾⁽²⁾ 0 0							
		X_L6	X L5 ⁽²⁾	X L4 ⁽²⁾	X L3 ⁽¹⁾⁽²⁾	0	0

1. If 12-bit mode is enabled, this bit is set to 0.

2. If 10-bit mode is enabled, this bit is set to 0.

The 8 least significant bits of linear acceleration sensor X-axis output. Together with the $OUT_X_H_A$ (29h) register it forms the output value expressed as a 16-bit word in 2's complement.

8.12 OUT_X_H_A (29h)

X-axis MSB output register (r)

Table 53. OUT_X_H_A register default values

				-			
X_H7	X_H6	X_H5	X_H4	X_H3	X_H2	X_H1	X_H0

The 8 most significant bits of linear acceleration sensor X-axis output. Together with the $OUT_X_L_A$ (28h) register it forms the output value expressed as a 16-bit word in 2's complement.

8.13 OUT_Y_L_A (2Ah)

Y-axis LSB output register (r)

Table 54. OUT_Y_L_A register default values

V I 7	VIG	$V = E^{(2)}$	\mathbf{V} \mathbf{I} \mathbf{A} (2)	$v_{12}(1)(2)$	$v_{12}(1)(2)$	0	0
1_L/						0	0

1. If 12-bit mode is enabled, this bit is set to 0.

2. If 10-bit mode is enabled, this bit is set to 0.

The 8 least significant bits of linear acceleration sensor Y-axis output. Together with the $OUT_Y_H_A$ (2Bh) register it forms the output value expressed as a 16-bit word in 2's complement.

8.14 OUT_Y_H_A (2Bh)

Y-axis MSB output register (r)

	Т	able 55. Ol	JT_Y_H_A	register de	fault value	s	
Y_H7	Y_H6	Y_H5	Y_H4	Y_H3	Y_H2	Y_H1	Y_H0

The 8 most significant bits of linear acceleration sensor Y-axis output. Together with the $OUT_Y_L_A$ (2Ah) register it forms the output value expressed as a 16-bit word in 2's complement.

58/82	DocID027766 Rev 7	

8.15 OUT_Z_L_A (2Ch)

Z-axis LSB output register (r)

Table 56	OUT Z L	A register	default values

1. If 12-bit mode is enabled, this bit is set to 0.

2. If 10-bit mode is enabled, this bit is set to 0.

The 8 least significant bits of linear acceleration sensor Z-axis output. Together with the $OUT_Z_H_A$ (2Dh) register it forms the output value expressed as a 16-bit word in 2's complement.

8.16 OUT_Z_H_A (2Dh)

ſ

Z-axis MSB output register (r)

Table 57. OUT_Z_H_A register default values

Z_H7	Z_H6	Z_H5	Z_H4	Z_H3	Z_H2	Z_H1	Z_H0

The 8 most significant bits of linear acceleration sensor Z-axis output. Together with the $OUT_Z_L_A$ (2Ch) register it forms the output value expressed as a 16-bit word in 2's complement.

8.17 FIFO_THS_A (2Eh)

FIFO threshold level setting (r/w).

		Table	e 58. FIFO_	THS_A reg	ister		
FTH7	FTH6	FTH5	FTH4	FTH3	FTH2	FTH1	FTH0

8.18 FIFO_SRC_A (2Fh)

FIFO_SRC register (r)

Table	59.	FIFO	SRC	A re	aister
Table	55.				gister

FTH FIFO OVR DIFF8	-	-



FTH	FIFO threshold status.
	(0: FIFO filling is lower than FTH level; 1: FIFO filling is equal to or higher than threshold level)
OVR	FIFO overrun status. (0: FIFO is not completely filled; 1: FIFO is completely filled and at least one sample has been overwritten)
DIFF8	Concatenated with <i>FIFO_SAMPLES_A (30h)</i> register, it represents the number of unread samples stored in FIFO. (000000000 = FIFO empty; 100000000 = FIFO full, 256 unread samples).

Table 60. FIFO_SRC register description

8.19 FIFO_SAMPLES_A (30h)

FIFO_SAMPLES control register (r)

Table 61. FIFO_SAMPLES_A register

DIFF7 DIFF6 DIFF5 DIFF4 DIFF3 DIFF2 DIFF1 DIFF0					0		
	DIFF7	DIFF6	DIFF4	DIFF3		DIFF1	

Table 62. FIFO_SAMPLES_A register description

 Concatenated with DIFF8 bit in <i>FIFO_SRC_A (2Fh)</i> register, it represents the number of unread samples stored in FIFO. (000000000 = FIFO empty;
100000000 = FIFO full, 256 unread samples).

8.20 TAP_6D_THS_A (31h)

4D configuration enable and TAP threshold configuration (r/w)

Table 63. TAP_6D_THS_A register

4D_EN 6D_THS1 6D_THS0	TAP_	TAP_	TAP_	TAP_	TAP_
	THS4	THS3	THS2	THS1	THS0

Table 64. TAP_6D_THS_A register description

4D_EN	4D detection portrait/landscape position enable. (0: no position detected; 1: portrait/landscape detection and face-up/face-down position enabled).	
6D_THS [1:0]	Thresholds for 4D/6D function @ FS=2 g (refer to Table 65)	
TAP_THS [4:0]	Threshold for TAP recognition @FS=2 g	

Table 65. 4D/6D threshold setting FS @ 2 g

6D_THS1	6D_THS0	Threshold decoding (degrees)
0	0	6 (80 degrees)
0	1	11 (70 degrees)
1	0	16 (60 degrees)
1	1	21 (50 degrees)



8.21 INT_DUR_A (32h)

Interrupt duration register (r/w)

Table 66. INT_DUR_A register

LAT3 LAT2 LAT1 LAT0 QUIET1 QUIET0	SHOCK1	SHOCK0				

Table 67. INT_DUR_A register description

LAT [3:1]	Duration of maximum time gap for double-tap recognition. When double-tap recognition is enabled, this register expresses the maximum time between two successive detected taps to determine a double-tap event. 1 LSB = 32 TODR.
QUIET [1:0]	Expected quiet time after a tap detection: this register represents the time after the first detected tap in which there must not be any over-threshold event. 1 LSB = 4 TODR.
SHOCK [4:0]	Maximum duration of over-threshold event: this register represents the maximum time of an over-threshold signal detection to be recognized as a tap event. 1 LSB = 8 TODR

8.22 WAKE_UP_THS_A (33h)

Wakeup threshold register (r/w)

Table 68. WAKE_UP_THS_A register

SINGLE_ DOUBLE_ TAP	WU_ THS_4	WU_ THS_3	WU_ THS 2	WU_ THS 1	WU_ THS 0
---------------------------	--------------	--------------	--------------	--------------	--------------

Table 69. WAKE_UP_THS_A register description

SINGLE_ DOUBLE_ TAP	Double/single-tap event detection: (0: double-tap event detection; 1: single-tap event detection)
SLEEP_ON	Sleep (inactivity) enable
	(0: sleep disabled; 1: sleep enabled)
WU_THS [5:0]	Wakeup threshold



8.23 WAKE_UP_DUR_A (34h)

Wakeup and sleep duration configuration register (r/w)

FF_DUR5 WU_DUR1 WU_DUR0	INT1_	SLEEP_	SLEEP_	SLEEP_	SLEEP_
	FSS7	DUR3	DUR2	DUR1	DUR0

Table 71. WAKE_UP_DUR_A register description

FF DUR5	Free-fall duration. In conjunction with FF_DUR [4:0] bit in <i>FREE_FALL_A</i> (35h) register. 1 LSB = 1 TODR			
WU_DUR [1:0]	Wakeup duration. 1 LSB = 1 TODR			
INT1_FSS7	FF interrupt is routed on INT1 pad (0: disabled; 1: enabled)			
SLEEP_DUR[5:0]	Duration to go in sleep mode. 1 LSB = 512 TODR			

8.24 FREE_FALL_A (35h)

Free-fall duration and threshold configuration register (r/w)

Table 72. FREE_FALL_A register

				—	0		
FF_DUR4	FF_DUR3	FF_DUR2	FF_DUR1	FF_DUR0	FF_THS2	FF_THS1	FF_THS0

Table 73. FREE_FALL_A register description

FF_DUR [4:0]	Free-fall duration. In conjunction with FF_DUR5 bit in <i>WAKE_UP_DUR_A (34h)</i> register. 1 LSB = 1 TODR.
FF_THS [2:0]	Free-fall threshold @ FS = 2 g (refer to Table 74)

Table 74. FREE_FALL_A threshold decoding @ 2 g FS

FF_THS1	FF_THS1	FF_THS0	Threshold decoding (degrees)
0	0	0	5
0	0	1	7
0	1	0	8
0	1	1	10
1	0	0	11
1	0	1	13
1	1	0	15
1	1	1	16



8.25 STATUS_DUP_A (36h)

Event detection status register (r)

Table 75. STATUS_DUP_A register

OVR	WU_IA	SLEEP_ STATE	DOUBLE_ TAP	SINGLE_ TAP	6D_IA	FF_IA	DRDY
-----	-------	-----------------	----------------	----------------	-------	-------	------

Table 76. STATUS_DUP_A register description

OVR	FIFO overrun status flag. (0: FIFO filling is not completely filled; 1: FIFO is completely filled and at least one sam- ple has been overwritten)
WU_IA	Wakeup event detection status. (0: WU event not detected; 1: Wake up event detected)
SLEEP_ STATE	Sleep event status. (0: Sleep event not detected; 1: Sleep event detected)
DOUBLE_ TAP	Double-tap event status: (0: Double-tap event not detected; 1: Double-tap event detected)
SINGLE_ TAP	Single-tap event status: (0: Single-tap event not detected; 1: Single-tap event detected)
6D_IA	Source of change in position portrait/landscape/face-up/face-down. (0: no event detected; 1: a change in position is detected)
FF_IA	Free-fall event detection status. (0: free-fall event not detected; 1: free-fall event detected)
DRDY	Data-ready status. (0: not ready; 1: X-, Y- and Z-axis new data available)



8.26 WAKE_UP_SRC_A (37h)

Wakeup source register (r)

Table 77	WAKE	UP	SRC	Α	register
10010 111				_	

-	-	FF_IA	SLEEP STATE IA	WU_IA	X_WU	Y_WU	Z_WU
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Table 78. WAKE_UP_SRC_A register description

FF_IA	Free-fall event detection status. (0: FF event not detected; 1: FF event detected)
SLEEP STATE IA	Sleep event status. (0: Sleep event not detected; 1: Sleep event detected)
WU_IA	Wakeup event detection status. (0: Wakeup event not detected; 1: Wakeup event is detected)
X_WU	Wakeup event detection status on X-axis. (0: Wakeup event on X not detected; 1: Wakeup event on X-axis is detected)
Y_WU	Wakeup event detection status on Y-axis. (0: Wakeup event on Y not detected; 1: Wake up event on Y-axis is detected)
Z_WU	Wakeup event detection status on Z-axis. (0: Wakeup event on Z not detected; 1: Wake up event on Z-axis is detected)

8.27 TAP_SRC_A (38h)

TAP source register (r)

Table 79. TAP_SRC_A register

-	TAP_IA	SINGLE TAP	DOUBLE TAP	TAP SIGN	X_TAP	Y_TAP	Z_TAP
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Table 80. TAP_SRC_A register description

TAP_IA	TAP event status. (0: Tap event not detected; 1: Tap event detected)
SINGLE TAP	Single-tap event status. (0: Single-tap event not detected; 1: Single-tap event detected)
DOUBLE TAP	Double-tap event status. (0: Double-tap event not detected; 1: Double-tap event detected)
TAP_SIGN	Sign of acceleration detected by tap event. (0: positive sign of acceleration detected; 1: negative sign of acceleration detected).
X_TAP	Tap event detection status on X-axis. (0: Tap event on X not detected; 1: Tap event on X-axis is detected)
Y_TAP	Tap event detection status on Y-axis. (0: Tap event on Y not detected; 1: TAP event on Y-axis is detected)
Z_TAP	Tap event detection status on Z-axis. (0: Tap event on Z not detected; 1: Tap event on Z-axis is detected)



8.28 6D_SRC_A (39h)

6D source register (r)

Table	81.	6D	SRC	Α	register
10010	••••	~-	_01.0_	_	i ogiotoi

- 6D_IA ZH ZL YH YL XH XL

Table 82. 6D_SRC_A register description

6D_IA	Source of change in position portrait/landscape/face-up/face-down. (0: no event detected; 1: a change in position is detected)
ZH	ZH over threshold (0: ZH does not exceed the threshold; 1: ZH is over the threshold)
ZL	ZL over threshold (0: ZL does not exceed the threshold; 1: ZL is over the threshold)
YH	YH over threshold (0: YH does not exceed the threshold; 1: YH is over the threshold)
YL	YL over threshold (0: YL does not exceed the threshold; 1: YL is over the threshold)
ХН	XH over threshold: (0: XH does not exceed the threshold; 1: XH is over the threshold)
XL	XL over threshold (0: XL does not exceed the threshold; 1: XL is over the threshold)

8.29 STEP_COUNTER_MINTHS_A (3Ah)

Step counter configuration register (r/w).

Table 83. STEP_COUNTER_MINTHS_A configuration register

RST_ nSTEPPEDO4gSC_ MTHS5SC_ MTHS4SC_ MTHS3SC_ MTHS2SC_ MTHS2SC_ MTHS1SC_ MTHS1						
	PEDO4g	SC_	SC_	SC_	 SC_	SC_

Table 84. STEP_COUNTER_MINTHS_A configuration register description

RST_nSTEP	Step number synchronous reset bit: when '1'-logic forces pedometer to reset the number of steps in <i>STEP_COUNTER_L_A (3Bh)</i> and <i>STEP_COUNTER_H_A (3Ch)</i> registers. Default value: 0
PEDO4g	 4 g operation mode for pedometer routines enable. Default: 0 (0: 4 g operation mode for pedometer routines disabled; 1: 4 g operation mode for pedometer routines enabled)
SC_MTHS [5:0]	Minimum threshold value for step counter routine. Default: 01 0000



8.30 STEP_COUNTER_L_A (3Bh)

Step counter register (r)

Table 85. STEP_COUNTER_L_A configuration register

| nSTEP_ |
|--------|--------|--------|--------|--------|--------|--------|--------|
| L7 | L6 | L5 | L4 | L3 | L2 | L1 | L0 |

Table 86. STEP_COUNTER_L_A configuration register description

nSTEP_L [7:0]	Least significant part of number of steps detected by step counter routine.	l
	Unsigned representation.	

8.31 STEP_COUNTER_H_A (3Ch)

Step counter register (r)

Table 87. STEP_COUNTER_H_A register

| nSTEP_ |
|--------|--------|--------|--------|--------|--------|--------|--------|
| H7 | H6 | H5 | H4 | H3 | H2 | H1 | H0 |

Table 88. STEP_COUNTER_H_A register description

 Most significant part of number of steps detected by step counter routine. Unsigned representation.

8.32 FUNC_CK_GATE_A (3Dh)

Functional source register (r)

Table 89. FUNC_CK_GATE_A register

TILT_INT FS_SRC_1 FS_SRC_0	SIG_MOT	RST_SIGN	RST_	STEP_	CK_GATE
	_ DETECT	_MOT	PEDO	DETECT	_FUNC



TILT_INT	Tilt event detection status. (0: tilt event not detected; 1: tilt event detected)
FS_ SRC [1:0]	Full-scale SRC bit. (00: Same as <i>CTRL1_A</i> (20h) - no scaling; 01: 2 g; 10: 4 g; 11: same as <i>CTRL1_A</i> (20h) - no scaling)
SIGN_MOT_ DETECT	Significant motion event detection status. (0: significant motion event not detected; 1: significant motion event detected)
RST_SIGN MOT	Significant motion initialization reset. (0: disabled; 1: pedometer significant motion initialization has to be executed at the next routine execution or is actually ongoing)
RST_PEDO	Pedometer reset. (0: disabled; 1: indicates that pedometer step counter initialization has to be executed at the next routine execution or is actually ongoing)
STEP_DETECT	Step detection status. (0: Step not detected; 1: Step detected)
CK_GATE_ FUNC	Function clocking gate signal. (0: Power down; 1: FUNC is in power mode)

Table 90. FUNC_CK_GATE_A register description

8.33 FUNC_SRC_A (3Eh)

Functional source register (r)

Table 91. FUNC_SRC_A register

-	-	-	-	-	RST_TILT	MODULE_ READY	-

Table 92. FUNC_SRC_A register description

RST_TILT	Tilt reset. (0: disabled; 1: indicates that tilt initialization has to be executed at the next routine execution or is actually ongoing)
MODULE_READY	Module status. (0: new module data not available, 1: new module data available)



8.34 FUNC_CTRL_A (3Fh)

Functional control register (r/w)

Table 93.	FUNC_	CTRL_A	register
-----------	-------	--------	----------

0 ⁽¹⁾	0 ⁽¹⁾	MODULE_ ON	TILT_ON	0 ⁽¹⁾	0 ⁽¹⁾	SIGN_ MOT_ON	STEP_ CNT_ON
------------------	------------------	---------------	---------	------------------	------------------	-----------------	-----------------

Table 94, FUNC CTRL A register description

1. This bit must be set to '0' for the correct operation of the device.

MODULE_ON	Module processing enable. Default value: 0 (0: disabled; 1: module)
TILT_ON	Tilt on. Default value: 0 (0: new module data not available; 1: new module data available)
SIGN_MOT_ON	Pedometer significant motion routine enable. Default value: 0 (0: disabled, 1: pedometer significant motion routine enabled)
STEP_CNT_ON	Step counter routine enable. Default value: 0 (0: disabled, 1: pedometer step counter routine enabled)

8.35 OFFSET_X_REG_L_M (45h) and OFFSET_X_REG_H_M (46h)

These registers comprise a 16-bit register and represent X hard-iron offset in order to compensate environmental effects (data in two's complement). These values act on the magnetic output data value in order to delete the environmental offset.

8.36 OFFSET_Y_REG_L_M (47h) and OFFSET_Y_REG_H_M (48h)

These registers comprise a 16-bit register and represent Y hard-iron offset in order to compensate environmental effects (data in two's complement). These values act on the magnetic output data value in order to delete the environmental offset.

8.37 OFFSET_Z_REG_L_M (49h) and OFFSET_Z_REG_H_M (4Ah)

These registers comprise a 16-bit register and represent Z hard-iron offset in order to compensate environmental effects (data in two's complement). These values act on the magnetic output data value in order to delete the environmental offset.

8.38 WHO_AM_I_M (4Fh)

The identification register is used to identify the device (read-only register).

0	1	0	0	0	0	0	0
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68/82



8.39 CFG_REG_A_M (60h)

The configuration register is used to configure the output data rate and the measurement configuration.

		Table 98	5. CFG_RE	G_A_M re	gister		
COMP_ TEMP_EN	REBOOT	SOFT_RST	LP	ODR1	ODR0	MD1	MD0

	Table 50. CFG_REG_A_IN register description
COMP_ TEMP_EN ⁽¹⁾	Enable the magnetometer temperature compensation. Default value: 0 (0: temperature compensation disabled; 1: temperature compensation enabled)
REBOOT	Reboot magnetometer memory content. Default value: 0 (0: normal mode; 1: reboot memory content)
SOFT_RST	When this bit is set, the configuration registers and user registers are reset. Flash registers keep their values.
LP	Low-power mode enable. Default: 0 0: high-resolution mode 1: low-power mode enabled
ODR[1:0]	Output data rate configuration (see Table 97: Output data rate configuration)
MD[1:0]	Mode select bit. These bits select the mode of operation of the device (see <i>Table 98: System mode</i>)

Table 96. CFG_REG_A_M register description

1. For proper operation, this bit must be set to '1'.

Table 97	Output	data rate	configuration
----------	--------	-----------	---------------

ODR1	ODR0	ODR (Hz)
0	0	10 (default)
0	1	20
1	0	50
1	1	100

Table 98. System mode

MD1	MD0	Mode
0	0	Continuous mode. In continuous mode the device continuously performs measurements and places the result in the data register. The data-ready signal is generated when a new data set is ready to be read. This signal can be available on the external pin by setting the INT_MAG bit in $CFG_REG_C_M$ (62h).
0	1	Single mode. When single mode is selected, the device performs a single measurement, sets DRDY high and returns to idle mode. Mode register return to idle mode bit values.
1	0	Idle mode. Device is placed in idle mode. I ² C and SPI active.
1	1	Idle mode. Device is placed in idle mode. I ² C and SPI active.



8.40 CFG_REG_B_M (61h)

Table 99. CFG_REG_B_M register

0	0	0	OFF_ CANC_ ONE_ SHOT	INT_on_ DataOFF	Set_FREQ	OFF_CANC	LPF

Table 100. CFG_REG_B_M register description

OFF_CANC_ ONE_SHOT	Enables offset cancellation in single measurement mode. The OFF_CANC bit must be set to 1 when enabling offset cancellation in single measurement mode. 0: offset cancellation in single measurement mode disabled; 1: offset cancellation in single measurement mode enabled.
INT_on_ DataOFF	If '1', the interrupt block recognition checks data after the hard-iron correction to discover the interrupt.
Set_FREQ	Selects the frequency of the set pulse. 0: set pulse is released every 63 ODR; 1: set pulse is released only at power-on after PD condition.
OFF_CANC	Enables offset cancellation.
LPF	Low-pass filter enable (see <i>Table 101</i>) 0: digital filter disabled; 1: digital filter enabled

Table 101. Digital low-pass filter

CFG_REG_B[LPF]	BW [Hz]
0 (disable)	ODR/2
1 (enable)	ODR/4



8.41 CFG_REG_C_M (62h)

Table	102	CFG	RFG	С	Мr	egister
Table	102.	0.0				cyister

0	INT_MAG _PIN	I2C_DIS	BDU	BLE	0 ⁽¹⁾	Self_test	INT_MAG

1. This bit must be set to '0' for the correct operation of the device.

Table 103. CFG_REG_C_M register description

INT_MAG_PIN	If '1', the INTERRUPT signal (INT bit inside <i>INT_SOURCE_REG_M</i> (64h) is driven on INT_MAG_PIN.
I2C_DIS	If '1', the I^2C interface is inhibited. Only the SPI interface can be used.
BDU	If enabled, reading of incorrect data is avoided when the user reads asynchro- nously. In fact if the read request arrives during an update of the output data, a latch is possible, reading incoherent high and low parts of the same register. Only one part is updated and the other one remains old.
BLE	If '1', an inversion of the low and high parts of the data occurs.
Self_test	If '1', the self-test is enabled.
INT_MAG	If '1', the DRDY pin is configured as a digital output.

8.42 INT_CTRL_REG_M (63h)

The interrupt control register is used to enable and to configure the interrupt recognition.

Table 104. INT_CRTL_REG_M register

XIEN	YIEN	ZIEN	0 ⁽¹⁾	0 ⁽¹⁾	IEA	IEL	IEN
				•			

1. This bit must be set to '0' for the correct operation of the device.

Table 105. INT_CTRL_REG_M register description

XIEN	Enables the interrupt recognition for the X-axis. Default: 0 1: enabled; 0: disabled.
YIEN	Enables the interrupt recognition for the Y-axis. Default: 0 1: enabled; 0: disabled.
ZIEN	Enables the interrupt recognition for the Z-axis. Default: 0 1: enabled; 0: disabled.
IEA	Controls the polarity of the INT bit (<i>INT_SOURCE_REG_M (64h)</i>) when an interrupt occurs. Default: 0 If IEA = 0, then INT = 0 signals an interrupt If IEA = 1, then INT = 1 signals an interrupt
IEL	Controls whether the INT bit (<i>INT_SOURCE_REG_M</i> (64h)) is latched or pulsed. Default: 0 If IEL = 0, then INT is pulsed. If IEL = 1, then INT is latched. Once latched, INT remains in the same state until <i>INT_SOURCE_REG_M</i> (64h) is read.
IEN	Interrupt enable. When set, enables the interrupt generation. The INT bit is in <i>INT_SOURCE_REG_M (64h)</i> . Default: 0



8.43 INT_SOURCE_REG_M (64h)

When interrupt latched is selected, reading this register resets all the bits in this register.

Table 106. INT_SOURCE_REG_M register									
P_TH_S_	P_TH_S_	P_TH_S_	N_TH_S_	N_TH_S_	N_TH_S_	MROI	INT		
Х	Y	Z	X	Y	Z	MROI			

Table 107. INT_SOURCE_REG_M register description

P_TH_S_X	X-axis value exceeds the threshold positive side
P_TH_S_Y	Y-axis value exceeds the threshold positive side
P_TH_S_Z	Z-axis value exceeds the threshold positive side
N_TH_S_X	X-axis value exceeds the threshold negative side
N_TH_S_Y	Y-axis value exceeds the threshold negative side
N_TH_S_Z	Z-axis value exceeds the threshold negative side
MROI	MROI flag generation is alway enabled. This flag is reset by reading <i>INT_SOURCE_REG_M</i> (64 <i>h</i>).
INT	This bit signals when the interrupt event occurs.

8.44 INT_THS_L_REG_M (65h)

This register contains the least significant bits of the threshold value chosen for the interrupt.

Table 108. INT_THS_L_REG_M register									
TH7	THS6	TH5	TH4	TH3	TH2	TH1	TH0		

Table 109. INT_THS_L_REG_M register description

 TH[7:0]
 Threshold value for the interrupt.

8.45 INT_THS_H_REG_M (66h)

This register contains the most significant bits of the threshold value chosen for the interrupt.

Table 110. INT_THS_H_REG_M register

TH15 THS14 TH13 TH12 TH11 TH10	TH9	TH8									

Table 111. INT_THS_H_REG_M register description

TH[15:8]	Threshold value for the interrupt.

These registers set the threshold value for the output to generate the interrupt (INT bit in *INT_SOURCE_REG_M (64h)*). This threshold is common to all three (axes) output values and is unsigned unipolar. The threshold value is correlated to the current gain and it is unsigned because the threshold is considered as an absolute value but crossing the threshold is detected for both positive and negative sides.



8.46 STATUS_REG_M (67h)

The status register is an 8-bit read-only register. This register is used to indicate device status. SR0 through SR7 indicate bit locations, with SR denoting the bits that are in the status register. SR7 denotes the first bit of the data stream.

Table 112.	STATUS	REG	Μ	register

Zyxor	zor	yor	xor	Zyxda	zda	yda	xda		

Table 113. STATUS_REG_M register description

Zyxor	X-, Y- and Z-axis data overrun. Default value: 0 (0: no overrun has occurred; 1: a new set of data has overwritten the previous set).
zor	Z-axis data overrun. Default value: 0 (0: no overrun has occurred; 1: new data for the Z-axis has overwritten the previous data).
yor	Y-axis data overrun. Default value: 0 (0: no overrun has occurred; 1: new data for the Y-axis has overwritten the previous data).
xor	X-axis data overrun. Default value: 0 (0: no overrun has occurred; 1: new data for the X-axis has overwritten the previous data).
Zyxda	X-, Y- and Z-axis new data available. Default value: 0 (0: a new set of data is not yet available; 1: a new set of data is available).
zda	Z-axis new data available. Default value: 0 (0: a new data for the Z-axis is not yet available; 1: a new data for the Z-axis is available)
yda	Y-axis new data available. Default value: 0 (0: a new data for the Y-axis is not yet available; 1: a new data for the Y-axis is available)
xda	X-axis new data available. Default value: 0 (0: a new data for the X-axis is not yet available; 1: a new data for the X-axis is available)

8.47 OUTX_L_REG_M, OUTX_H_REG_M (68h - 69h)

The data output X registers are two 8-bit registers, data output ch1 MSB register (69h) and output X LSB register (68h).

The output data represents the raw magnetic data only if OFFSET_X_REG is equal to zero, otherwise hard-iron calibration is included.

Table 114. OUTX_L_REG_M register									
0	0	0	0	0	0	0	0		

Table 115. OUTX_H_REG_M register										
0	0	0	0	0	0					

The value of the magnetic field is expressed in two's complement. This register contains the X component of the magnetic data.



0

0

8.48 OUTY_L_REG_M, OUTY_H_REG_M (6Ah - 6Bh)

The data output Y registers are two 8-bit registers, data output ch1 MSB register (6Bh) and output Y LSB register (6Ah).

The output data represents the raw magnetic data only if OFFSET_Y_REG is equal to zero, otherwise hard-iron calibration is included.

		Table 116	6. OUTY_L	_REG_M r	egister		
0	0	0	0	0	0	0	0

Table 117. OUTY_H_REG_M register

|--|

The value of the magnetic field is expressed in two's complement. This register contains the Y component of the magnetic data.

8.49 OUTZ_L_REG_M, OUTZ_H_REG_M (6Ch - 6Dh)

The data output Z registers are two 8-bit registers, data output ch1 MSB register (6Bh) and output Z LSB register (6Ah).

The output data represents the raw magnetic data only if OFFSET_Z_REG is equal to zero, otherwise hard-iron calibration is included.

		Table 118	B. OUTZ_L	_REG_M re	egister		
0	0	0	0	0	0	0	0

Table 119. OUTZ_H_REG_M register

					- <u>g</u>		-
0	0	0	0	0	0	0	0

The value of the magnetic field is expressed in two's complement. This register contains the Z component of the magnetic data.



9 Advanced configuration register mapping

The table below provides a list of the registers for advanced configuration functions available in the device and the corresponding addresses.

Advanced configuration registers are accessible when FUNC_CFG_EN is set to '1' in *CTRL2_A (21h)*. Once enabled, access to the advanced configuration registers can be disabled by setting the FUNC_CFG_EN bit to '1' in *CTRL2_A (3Fh)*.

	•					
Name	Туре	Register address		Default	Comment	
Name	Type	Hex	Binary	Delault	Comment	
RESERVED	R/W	00-2A				
PEDO_DEB_REG_A	R/W	2B	00101011	01101110		
RESERVED	R/W	2C-33				
SM_THS_A	R/W	34	00110100	00000110		
RESERVED	R/W	35-39				
STEP_COUNT_DELTA_A	R/W	3A	00111010	00000000		
RESERVED	R/W	3B-3E				
CTRL2_A (3Fh)	R/W	3F	00111111	00010100		

Table 120. Register map - advanced configuration functions

Registers marked as *Reserved* must not be changed. Writing to those registers may cause permanent damage to the device.

The content of the registers that are loaded at boot should not be changed. They contain the factory calibration values. Their content is automatically restored when the device is powered up.



10 Advanced configuration registers description

10.1 PEDO_DEB_REG_A (2Bh)

Table 121. PEDO_DEB_REG_A register default values

| DEB_ |
|-------|-------|-------|-------|-------|-------|-------|-------|
| TIME4 | TIME3 | TIME2 | TIME1 | TIME0 | STEP2 | STEP1 | STEP0 |

Table 122. PEDO_DEB_REG_A register description

DEB_TIME[4:0]	Debounce time. If the time between two consecutive steps is greater than DEB_TIME*80ms, the debouncer is reactivated. Default value: 01101
DEB_STEP[2:0]	Debounce threshold. Minimum number of steps to increment step counter (debounce). Default value: 110

10.2 SM_THS_A (34h)

Defines the threshold value (r/w).

Table 123. SM_THS_A configuration register

| SM_THS |
|--------|--------|--------|--------|--------|--------|--------|--------|
| _7 | _6 | _5 | _4 | _3 | _2 | _1 | _0 |

Table 124. SM THS A configuration register description

These bits define the threshold value which corresponds to the number of steps to be performed by the user upon a change of location before the significant motion interrupt is generated. It is expressed as an 8-bit unsigned value. The default value of this field is equal to 6 (= 00000110b).

10.3 STEP_COUNT_DELTA_A (3Ah)

Step counter configuration register (r/w).

Table 125. STEP_COUNT_DELTA_A configuration register

			_		0		
STEP_							
COUNT_							
D7	D6	D5	D4	D3	D2	D1	D0
		1					

Table 126. STEP_COUNT_DELTA_A configuration register description

STEP_COUNT_D[7:0]	Period of time to detect at least one step to generate step recognition.
	Default value: 0
	1 LSB = 1.6384 s



10.4 CTRL2_A (3Fh)

Functional control register (r/w)

		Table 127	. CTRL2_A	configura	tion regist	er	
BOOT ⁽¹⁾	SOFT RESET ⁽¹⁾	0 ⁽²⁾	FUNC_ CFG_EN	FDS_ SLOPE ⁽¹⁾	IF_ADD_ INC ⁽¹⁾	I2C_ DISABLE ⁽¹⁾	SIM ⁽¹⁾

1. Read-only bits

2. This bit must be set to '0' for the correct operation of the device.

Table 120. OTTEL_A configuration register description		
BOOT	Forces the reboot of the flash content in the trimming and configuration registers. READ ONLY.	
SOFT_RESET	Soft reset acts as a reset for all control registers, then goes to 0. READ ONLY.	
FUNC_CFG_EN	Default value: 1 (0: disable pedometer/sensor hub advanced functionalities; 1: enable pedometer/sensor hub advanced functionalities)	
FDS_SLOPE	High-pass filter data selection on output register and FIFO. READ ONLY.	
IF_ADD_INC	Register address automatically incremented during multiple byte access with a serial interface (I ² C or SPI). READ ONLY.	
I2C_DISABLE	Disable I ² C communication protocol. READ ONLY.	
SIM	SPI serial interface mode selection. READ ONLY.	

Table 128. CTRL2_A configuration register description



11 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK is an ST trademark.

11.1 LGA-12 package information



Figure 21. LGA-12 2x2x1 mm package outline and mechanical data





11.2 LGA-12 packing information



Figure 22. Carrier tape information for LGA-12 package

Figure 23. LGA-12 package orientation in carrier tape







Figure 24. Reel information for carrier tape of LGA-12 package

Reel dimensions (mm)			
A (max)	330		
B (min)	1.5		
С	13 ±0.25		
D (min)	20.2		
N (min)	60		
G	12.4 +2/-0		
T (max)	18.4		

80/82



12 Revision history

Date	Revision	Changes
31-Aug-2016	5	Document status promoted to production data Updated <i>Table 3: Sensor characteristics</i> Updated <i>Table 5: Electrical characteristics</i> Updated <i>A</i> _{POW} and A _{UNP} in <i>Table 9: Absolute maximum ratings</i> Updated <i>Table 11: Current consumption of operating modes</i> Updated <i>Table 16: Current consumption of operating modes</i> Updated <i>Section 4.1.1: Magnetometer power modes</i> Updated <i>Figure 5</i> and <i>Figure 6</i> Added <i>Table 19: Pin status</i> Updated default value of CTRL2_A (21h) in <i>Table 28: Register map</i> Updated default value of PEDO_DEB_REG_A (2Bh) and CTRL2_A (3Fh) in <i>Table 120: Register map - advanced configuration functions</i> Updated <i>PEDO_DEB_REG_A (2Bh)</i> Updated <i>STEP_COUNTER_MINTHS_A (3Ah)</i> Added <i>Section 11.2: LGA-12 packing information</i>
26-Sep-2016	6	Updated Section 4.1.2: Magnetometer offset cancellation and added OFF_CANC_ONE_SHOT bit to CFG_REG_B_M (61h) Updated Figure 21: LGA-12 2x2x1 mm package outline and mechanical data
28-Nov-2018	7	Updated Table 5: Electrical characteristics

Table 130. Document revision history



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